



---

# HT32F52342/HT32F52352 Datasheet

**32-Bit ARM® Cortex™-M0+ Microcontroller,  
up to 128 KB Flash and 16 KB SRAM with 1 MSPS ADC,  
USART, UART, SPI, I<sup>2</sup>C, I<sup>2</sup>S, MCTM, GPTM, BFTM,  
SCI, CRC, RTC, WDT, PDMA, EBI and USB2.0 FS**

Revision: V1.20 Date: October 14, 2016

[www.holtek.com](http://www.holtek.com)

## Table of Contents

<b>1</b>	<b>General Description</b>	<b>6</b>
<b>2</b>	<b>Features</b>	<b>7</b>
	Core	7
	On-chip Memory	7
	Flash Memory Controller – FMC	7
	Reset Control Unit – RSTCU	8
	Clock Control Unit – CKCU	8
	Power Management – PWRCU	8
	External Interrupt/Event Controller – EXTI	9
	Analog to Digital Converter – ADC	9
	Analog Comparator – CMP	9
	I/O Ports – GPIO	10
	Motor Control Timer – MCTM	10
	PWM Generation and Capture Timers – GPTM	11
	Single Channel Generation and Capture Timers – SCTM	11
	Basic Function Timer – BFTM	11
	Watchdog Timer – WDT	12
	Real Time Clock – RTC	12
	Inter-integrated Circuit – I <sup>2</sup> C	12
	Serial Peripheral Interface – SPI	13
	Universal Synchronous Asynchronous Receiver Transmitter – USART	13
	Universal Asynchronous Receiver Transmitter – UART	14
	Smart Card Interface – SCI	14
	Inter-IC Sound – I <sup>2</sup> S	15
	Cyclic Redundancy Check – CRC	15
	Peripheral Direct Memory Access – PDMA	16
	External Bus Interface – EBI	16
	Universal Serial Bus Device Controller – USB	17
	Debug Support	17
	Package and Operation Temperature	17
<b>3</b>	<b>Overview</b>	<b>18</b>
	Device Information	18
	Block Diagram	19
	Memory Map	20
	Clock Structure	23

<b>4 Pin Assignment</b> .....	<b>24</b>
<b>5 Electrical Characteristics</b> .....	<b>31</b>
Absolute Maximum Ratings .....	31
Recommended DC Operating Conditions .....	31
On-Chip LDO Voltage Regulator Characteristics.....	31
Power Consumption .....	32
Reset and Supply Monitor Characteristics.....	33
External Clock Characteristics.....	34
Internal Clock Characteristics .....	35
PLL Characteristics.....	36
Memory Characteristics .....	36
I/O Port Characteristics.....	36
ADC Characteristics .....	38
Comparator Characteristics .....	40
SCTM/GPTM/MCTM Characteristics.....	40
I <sup>2</sup> C Characteristics .....	41
SPI Characteristics .....	42
I <sup>2</sup> S Characteristics .....	43
USB Characteristics.....	45
<b>6 Package Information</b> .....	<b>46</b>
SAW Type 33-pin (4mm×4mm) QFN Outline Dimensions.....	47
48-pin LQFP (7mm×7mm) Outline Dimensions.....	48
64-pin LQFP (7mm×7mm) Outline Dimensions.....	49

## List of Tables

Table 1. Features and Peripheral List .....	18
Table 2. Register Map .....	21
Table 3. Pin Assignment for 33-pin QFN, 48/64-pin LQFP Package .....	27
Table 4. Pin Description .....	29
Table 5. Absolute Maximum Ratings .....	31
Table 6. Recommended DC Operating Conditions .....	31
Table 7. LDO Characteristics .....	31
Table 8. Power Consumption Characteristics .....	32
Table 9. V <sub>DD</sub> Power Reset Characteristics .....	33
Table 10. LVD/BOD Characteristics .....	33
Table 11. High Speed External Clock (HSE) Characteristics .....	34
Table 12. Low Speed External Clock (LSE) Characteristics .....	34
Table 13. High Speed Internal Clock (HSI) Characteristics .....	35
Table 14. Low Speed Internal Clock (LSI) Characteristics .....	35
Table 15. PLL Characteristics .....	36
Table 16. Flash Memory Characteristics .....	36
Table 17. I/O Port Characteristics .....	36
Table 18. ADC Characteristics .....	38
Table 19. Comparator Characteristics .....	40
Table 20. SCTM/GPTM/MCTM Characteristics .....	40
Table 21. I <sup>2</sup> C Characteristics .....	41
Table 22. SPI Characteristics .....	42
Table 23. I <sup>2</sup> S Characteristics .....	43
Table 24. USB DC Electrical Characteristics .....	45
Table 25. USB AC Electrical Characteristics .....	45

## List of Figures

Figure 1. Block Diagram .....	19
Figure 2. Memory Map.....	20
Figure 3. Clock Structure .....	23
Figure 4. 33-pin QFN Pin Assignment .....	24
Figure 5. 48-pin LQFP Pin Assignment.....	25
Figure 6. 64-pin LQFP Pin Assignment.....	26
Figure 7. ADC Sampling Network Model .....	39
Figure 8. I <sup>2</sup> C Timing Diagrams .....	41
Figure 9. SPI Timing Diagrams – SPI Master Mode .....	42
Figure 10. SPI Timing Diagrams – SPI Slave Mode with CPHA=1.....	43
Figure 11. Timing of I <sup>2</sup> S Master Mode.....	44
Figure 12. Timing of I <sup>2</sup> S Slave Mode .....	44
Figure 13. USB Signal Rise Time and Fall Time and Cross-Point Voltage (VCRS) Definition .....	45

# 1 General Description

The HOLTEK HT32F52342/52352 devices are high performance, low power consumption 32-bit microcontrollers based around an ARM® Cortex™-M0+ processor core. The Cortex™-M0+ is a next-generation processor core which is tightly coupled with Nested Vectored Interrupt Controller (NVIC), SysTick timer, and including advanced debug support.

The devices operate at a frequency of up to 48 MHz with a Flash accelerator to obtain maximum efficiency. It provides up to 128 KB of embedded Flash memory for code/data storage and 16 KB of embedded SRAM memory for system operation and application program usage. A variety of peripherals, such as ADC, I<sup>2</sup>C, USART, UART, SPI, I<sup>2</sup>S, GPTM, MCTM, SCI, CRC-16/32, RTC, WDT, PDMA, EBI, USB2.0 FS, SW-DP (Serial Wire Debug Port), etc., are also implemented in the device series. Several power saving modes provide the flexibility for maximum optimisation between wakeup latency and power consumption, an especially important consideration in low power applications.

The above features ensure that the devices are suitable for use in a wide range of applications, especially in areas such as white goods application control, power monitors, alarm systems, consumer products, handheld equipment, data logging applications, motor control and so on.



## 2 Features

### Core

- 32-bit ARM® Cortex™-M0+ processor core
- Up to 48 MHz operating frequency
- 0.93 DMIPS/MHz (Dhrystone v2.1)
- Single-cycle multiplication
- Integrated Nested Vectored Interrupt Controller (NVIC)
- 24-bit SysTick timer

The Cortex™-M0+ processor is a very low gate count, highly energy efficient processor that is intended for microcontroller and deeply embedded applications that require an area optimized, low-power processor. The processor is based on the ARMv6-M architecture and supports Thumb® instruction sets; single-cycle I/O port; hardware multiplier and low latency interrupt respond time.

### On-chip Memory

- Up to 128 KB on-chip Flash memory for instruction/data and options storage
- 16 KB on-chip SRAM
- Supports multiple boot modes

The ARM® Cortex™-M0+ processor accesses and debug accesses share the single external interface to external AHB peripherals. The processor accesses take priority over debug accesses. The maximum address range of the Cortex™-M0+ is 4 GB since it has a 32-bit bus address width. Additionally, a pre-defined memory map is provided by the Cortex™-M0+ processor to reduce the software complexity of repeated implementation by different device vendors. However, some regions are used by the ARM® Cortex™-M0+ system peripherals. Refer to the ARM® Cortex™-M0+ Technical Reference Manual for more information. Figure 2 shows the memory map of the HT32F52342/52352 series of devices, including code, SRAM, peripheral, and other pre-defined regions.

### Flash Memory Controller – FMC

- Flash accelerator for maximum efficiency
- 32-Bit word programming with In System Programming Interface (ISP) and In Application Programming (IAP)
- Flash protection capability to prevent illegal access

The Flash Memory Controller, FMC, provides all the necessary functions and pre-fetch buffer for the embedded on-chip Flash Memory. Since the access speed of the Flash Memory is slower than the CPU, a wide access interface with a pre-fetch buffer and cache are provided for the Flash Memory in order to reduce the CPU waiting time which will cause CPU instruction execution delays. Flash Memory word program/page erase functions are also provided.

## Reset Control Unit – RSTCU

- Supply supervisor:
  - Power On Reset / Power Down Reset – POR/PDR
  - Brown-out Detector – BOD
  - Programmable Low Voltage Detector – LVD

The Reset Control Unit, RSTCU, has three kinds of reset, a power on reset, a system reset and an APB unit reset. The power on reset, known as a cold reset, resets the full system during power up. A system reset resets the processor core and peripheral IP components with the exception of the SW-DP controller. The resets can be triggered by an external signal, internal events and the reset generators.

## Clock Control Unit – CKCU

- External 4 to 16 MHz crystal oscillator
- External 32,768 Hz crystal oscillator
- Internal 8 MHz RC oscillator trimmed to  $\pm 2\%$  accuracy at 3.3V operating voltage and 25°C operating temperature
- Internal 32 kHz RC oscillator
- Integrated system clock PLL
- Independent clock divider and gating bits for peripheral clock sources

The Clock Control unit, CKCU, provides a range of oscillator and clock functions. These include a High Speed Internal RC oscillator (HSI), a High Speed External crystal oscillator (HSE), a Low Speed Internal RC oscillator (LSI), a Low Speed External crystal oscillator (LSE), a Phase Lock Loop (PLL), a HSE clock monitor, clock prescalers, clock multiplexers, APB clock divider and gating circuitry. The AHB, APB and Cortex™-M0+ clocks are derived from the system clock (CK\_SYS) which can come from the LSI, LSE, HSI, HSE or PLL. The Watchdog Timer and Real Time Clock (RTC) use either the LSI or LSE as their clock source.

## Power Management – PWRCU

- Single  $V_{DD}$  power supply : 2.0 V to 3.6 V
- Integrated 1.5 V LDO regulator for CPU core, peripherals and memories power supply
- VBAT battery power supply for RTC and backup registers
- Three power domains:  $V_{DD}$ , 1.5 V and Backup
- Four power saving modes: Sleep, Deep-Sleep1, Deep-Sleep2, Power-Down

Power consumption can be regarded as one of the most important issues for many embedded system applications. Accordingly the Power Control Unit, PWRCU, in these devices provides many types of power saving modes such as Sleep, Deep-Sleep1, Deep-Sleep2 and Power-Down mode. These operating modes reduce the power consumption and allow the application to achieve the best trade-off between the conflicting demands of CPU operating time, speed and power consumption.



## External Interrupt/Event Controller – EXTI

- Up to 16 EXTI lines with configurable trigger source and type
- All GPIO pins can be selected as EXTI trigger source
- Source trigger type includes high level, low level, negative edge, positive edge, or both edge
- Individual interrupt enable, wakeup enable and status bits for each EXTI line
- Software interrupt trigger mode for each EXTI line
- Integrated deglitch filter for short pulse blocking

The External Interrupt/Event Controller, EXTI, comprises 16 edge detectors which can generate a wake-up event or interrupt requests independently. Each EXTI line can also be masked independently.

## Analog to Digital Converter – ADC

- 12-bit SAR ADC engine
- Up to 1 Msps conversion rate
- Up to 12 external analog input channels

A 12-bit multi-channel ADC is integrated in the device. There are multiplexed channels, which include 12 external analog signal channels and 2 internal channels which can be measured. If the input voltage is required to remain within a specific threshold window, an Analog Watchdog function will monitor and detect these signals. An interrupt will then be generated to inform the device that the input voltage is not within the preset threshold levels. There are three conversion modes to convert an analog signal to digital data. The ADC can be operated in one shot, continuous and discontinuous conversion modes.

## Analog Comparator – CMP

- Rail-to-rail comparator
- Each comparator has configurable negative inputs used for flexible voltage selection
- Dedicated I/O pin or internal voltage reference provided by 6-bit scaler
- Programmable hysteresis
- Programming speed and consumption
- Comparator output can be output to I/O or to timers or ADC trigger inputs
- 6-bit scaler can be configurable to dedicated I/O for voltage reference
- Comparator has interrupt generation capability with wakeup from Sleep or Deep Sleep modes through the EXTI controller

The two general purpose comparators (CMP) are implemented within the device. They can be configured either as standalone comparators or combined with the different kinds of peripheral IPs. Each comparator is capable of asserting interrupts to the NVIC or waking up the MCU from sleep or deep sleep mode through the EXTI wakeup event management unit.

## I/O Ports – GPIO

- Up to 51 GPIOs
- Port A, B, C, D are mapped as 16 external interrupts - EXTI
- Almost all I/O pins have a configurable output driving current.

There are up to 51 General Purpose I/O pins, GPIO, named from PA0~PA15 to PD0~PD3 for the implementation of logic input/output functions. Each of the GPIO ports has a series of related control and configuration registers to maximise flexibility and to meet the requirements of a wide range of applications.

The GPIO ports are pin-shared with other alternative functions to obtain maximum functional flexibility on the package pins. The GPIO pins can be used as alternative functional pins by configuring the corresponding registers regardless of the input or output pins. The external interrupts on the GPIO pins of the device have related control and configuration registers in the External Interrupt Control Unit, EXTI.

## Motor Control Timer – MCTM

- One 16-bit up, down, up/down auto-reload counter
- 16-bit programmable prescaler allowing counter clock frequency division by any factor between 1 and 65536
- Input Capture function
- Compare Match Output
- PWM waveform generation with Edge-aligned and Center-aligned Counting Modes
- Single Pulse Mode Output
- Complementary Outputs with programmable dead-time insertion
- Supports 3-phase motor control and hall sensor interface
- Brake input to force the timer's output signals into a reset or fixed condition

The Motor Control Timer consists of a single 16-bit up/down counter, four 16-bit CCRs (Capture/Compare Registers), single one 16-bit counter-reload register (CRR), single 8-bit repetition counter and several control/status registers. It can be used for a variety of purposes including measuring the pulse widths of input signals or generating output waveforms such as compare match outputs, PWM outputs or complementary PWM outputs with dead-time insertion. The MCTM is capable of offering full functional support for motor control, hall sensor interfacing and brake input.

## PWM Generation and Capture Timers – GPTM

- One 16-bit up, down, up/down auto-reload counter
- 16-bit programmable prescaler allowing counter clock frequency division by any factor between 1 and 65536
- Input Capture function
- Compare Match Output
- PWM waveform generation with Edge-aligned and Center-aligned Counting Modes
- Single Pulse Mode Output
- Encoder interface controller with two inputs using quadrature decoder

The General Purpose Timer consists of one 16-bit up/down-counter, four 16-bit Capture/Compare Registers (CCRs), one 16-bit Counter Reload Register (CRR) and several control/status registers. They can be used for a variety of purposes including general time measurement, input signal pulse width measurement, output waveform generation such as single pulse generation, or PWM output generation. The GPTM supports an Encoder Interface using a decoder with two inputs.

## Single Channel Generation and Capture Timers – SCTM

- One 16-bit up and auto-reload counter
- One channel for each timer
- 16-bit programmable prescaler allowing counter clock frequency division by any factor between 1 and 65536
- Input Capture function
- Compare Match Output
- PWM waveform generation with Edge-aligned
- Single Pulse Mode Output

The Single-Channel Timer consists of one 16-bit up-counter, one 16-bit Capture/Compare Register (CCR), one 16-bit Counter-Reload Register (CRR) and several control/status registers. It can be used for a variety of purposes including general timer, input signal pulse width measurement or output waveform generation such as single pulse generation or PWM output.

## Basic Function Timer – BFTM

- One 32-Bit compare/match count-up counter – no I/O control features
- One shot mode – counting stops after a match condition
- Repetitive mode – restart counter after a match condition

The Basic Function Timer is a simple count-up 32-bit counter designed to measure time intervals and generate a one shot or repetitive interrupts. The BFTM operates in two functional modes, repetitive or one shot mode. In the repetitive mode the BFTM restarts the counter when a compare match event occurs. The BFTM also supports a one shot mode which forces the counter to stop counting when a compare match event occurs.

## Watchdog Timer – WDT

- 12-Bit down counter with 3-bit prescaler
- Reset event for the system
- Programmable watchdog timer window function
- Register write protection function

The Watchdog Timer is a hardware timing circuit that can be used to detect system failures due to software malfunctions. It includes a 12-bit count-down counter, a prescaler, a WDT delta value register, WDT operation control circuitry and a WDT protection mechanism. If the software does not reload the counter value before a Watchdog Timer underflow occurs, a reset will be generated when the counter underflows. In addition, a reset is also generated if the software reloads the counter when the counter value is greater than the WDT delta value. This means the counter must be reloaded within a limited timing window using a specific method. The Watchdog Timer counter can be stopped while the processor is in the debug mode. There is a register write protect function which can be enabled to prevent it from changing the Watchdog Timer configuration unexpectedly.

## Real Time Clock – RTC

- 32-Bit up-counter with a programmable prescaler
- Alarm function
- Interrupt and Wake-up event

The Real Time Clock, RTC, includes an APB interface, a 32-bit count-up counter, a control register, a prescaler, a compare register and a status register. Most of the RTC circuits are located in the Backup Domain except for the APB interface. The APB interface is located in the  $V_{DD15}$  power domain. Therefore, it is necessary to be isolated from the ISO signal that comes from the power control unit when the  $V_{DD15}$  power domain is powered off, that is when the device enters the Power-Down mode. The RTC counter is used as a wakeup timer to generate a system resume signal from the Power-Down mode.

## Inter-integrated Circuit – I<sup>2</sup>C

- Supports both master and slave modes with a frequency of up to 1 MHz
- Provide an arbitration function and clock synchronisation
- Supports 7-bit and 10-bit addressing modes and general call addressing
- Supports slave multi-addressing mode with maskable address

The I<sup>2</sup>C is an internal circuit allowing communication with an external I<sup>2</sup>C interface which is an industry standard two line serial interface used for connection to external hardware. These two serial lines are known as a serial data line, SDA, and a serial clock line, SCL. The I<sup>2</sup>C module provides three data transfer rates: 1. 100 kHz in the Standard mode, 2. 400 kHz in the Fast mode and 3. 1 MHz in the Fast plus mode. The SCL period generation register is used to setup different kinds of duty cycle implementations for the SCL pulse.

The SDA line which is connected directly to the I<sup>2</sup>C bus is a bi-directional data line between the master and slave devices and is used for data transmission and reception. The I<sup>2</sup>C also has an arbitration detect function and clock synchronisation to prevent situations where more than one master attempts to transmit data to the I<sup>2</sup>C bus at the same time.

## Serial Peripheral Interface – SPI

- Supports both master and slave mode
- Frequency of up to ( $f_{PCLK}/2$ ) MHz for the master mode and ( $f_{PCLK}/3$ ) MHz for the slave mode
- FIFO Depth: 8 levels
- Multi-master and multi-slave operation

The Serial Peripheral Interface, SPI, provides an SPI protocol data transmit and receive function in both master and slave mode. The SPI interface uses 4 pins, which are the serial data input and output lines, MISO and MOSI, the clock line, SCK, and the slave select line, SEL. One SPI device acts as a master device which controls the data flow using the SEL and SCK signals to indicate the start of data communication and the data sampling rate. To receive a data byte, the streamed data bits are latched on a specific clock edge and stored in the data register or in the RX FIFO. Data transmission is carried out in a similar way but in a reverse sequence. The mode fault detection provides a capability for multi-master applications.

## Universal Synchronous Asynchronous Receiver Transmitter – USART

- Supports both asynchronous and clocked synchronous serial communication modes
- Asynchronous operating baud rate up to ( $f_{PCLK}/16$ ) MHz and synchronous operating rate up to ( $f_{PCLK}/8$ ) MHz
- Full duplex communication
- Fully programmable serial communication characteristics including:
  - Word length: 7, 8, or 9-bit character
  - Parity: Even, odd, or no-parity bit generation and detection
  - Stop bit: 1 or 2 stop bit generation
  - Bit order: LSB-first or MSB-first transfer
- Error detection: Parity, overrun, and frame error
- Auto hardware flow control mode – RTS, CTS
- IrDA SIR encoder and decoder
- RS485 mode with output enable control
- FIFO Depth: 8 x 9 bits for both receiver and transmitter

The Universal Synchronous Asynchronous Receiver Transceiver, USART, provides a flexible full duplex data exchange using synchronous or asynchronous data transfer. The USART is used to translate data between parallel and serial interfaces, and is commonly used for RS232 standard communication. The USART peripheral function supports four types of interrupt including Line Status Interrupt, Transmitter FIFO Empty Interrupt, Receiver Threshold Level Reaching Interrupt and Time Out Interrupt. The USART module includes a transmitter FIFO, (TX\_FIFO) and receiver FIFO (RX\_FIFO). The software can detect a USART error status by reading the Line Status Register, LSR. The status includes the type and the condition of transfer operations as well as several error conditions resulting from Parity, Overrun, Framing and Break events.

## Universal Asynchronous Receiver Transmitter – UART

- Asynchronous serial communication operating baud-rate up to ( $f_{PCLK}/16$ ) MHz
- Full duplex communication
- Fully programmable serial communication characteristics including:
  - Word length: 7, 8, or 9-bit character
  - Parity: Even, odd, or no-parity bit generation and detection
  - Stop bit: 1 or 2 stop bit generation
  - Bit order: LSB-first or MSB-first transfer
- Error detection: Parity, overrun, and frame error

The Universal Asynchronous Receiver Transceiver, UART, provides a flexible full duplex data exchange using asynchronous transfer. The UART is used to translate data between parallel and serial interfaces, and is commonly used for RS232 standard communication. The UART peripheral function supports Line Status Interrupt. The software can detect a UART error status by reading the Line Status Register, LSR. The status includes the type and the condition of transfer operations as well as several error conditions resulting from Parity, Overrun, Framing and Break events.

## Smart Card Interface – SCI

- Supports ISO 7816-3 standard
- Character mode
- Single transmit buffer and single receive buffer
- 11-bit ETU (elementary time unit) counter
- 9-bit guard time counter
- 24-bit general purpose waiting time counter
- Parity generation and checking
- Automatic character retry on parity error detection in transmission and reception modes

The Smart Card Interface is compatible with the ISO 7816-3 standard. This interface includes Card Insertion/Removal detection, SCI data transfer control logic and data buffers, internal Timer Counters and corresponding control logic circuits to perform all the necessary Smart Card operations. The Smart Card interface acts as a Smart Card Reader to facilitate communication with the external Smart Card. The overall functions of the Smart Card interface are controlled by a series of registers including control and status registers together with several corresponding interrupts which are generated to get the attention of the microcontroller for SCI transfer status.

## Inter-IC Sound – I<sup>2</sup>S

- Master or slave mode
- Mono and stereo
- I2S-justified, Left-justified and Right-justified mode
- 8/16/24/32-bit sample size with 32-bit channel extended
- 8 x 32-bit Tx & Rx FIFO with PDMA supported
- 8-bit Fractional Clock Divider with rate control

The I<sup>2</sup>S is a synchronous communication interface that can be used as a master or slave to exchange data with other audio peripherals, such as ADCs or DACs. The I<sup>2</sup>S supports a variety of data formats. In addition to the stereo I2S-justified, Left-justified and Right-justified modes, there are mono PCM modes with 8/16/24/32-bit sample size. When the I<sup>2</sup>S operates in the master mode, then when using the fractional divider, it can provide an accurate sampling frequency output and support the rate control function and fine-tuning of the output frequency to avoid system problems caused by the cumulative frequency error between different devices.

## Cyclic Redundancy Check – CRC

- Support CRC16 polynomial: 0x8005,  
 $X^{16}+X^{15}+X^2+1$
- Support CCITT CRC16 polynomial: 0x1021,  
 $X^{16}+X^{12}+X^5+1$
- Support IEEE-802.3 CRC32 polynomial: 0x04C11DB7,  
 $X^{32}+X^{26}+X^{23}+X^{22}+X^{16}+X^{12}+X^{11}+X^{10}+X^8+X^7+X^5+X^4+X^2+X+1$
- Supports 1's complement, byte reverse & bit reverse operation on data and checksum
- Supports byte, half-word & word data size
- Programmable CRC initial seed value
- CRC computation executed in 1 AHB clock cycle for 8-bit data and 4 AHB clock cycles for 32-bit data
- Supports PDMA to complete a CRC computation of a block of memory

The CRC calculation unit is an error detection technique test algorithm which is used to verify data transmission or storage data correctness. A CRC calculation takes a data stream or a block of data as its input and generates a 16- or 32-bit output remainder. Ordinarily, a data stream is suffixed by a CRC code and used as a checksum when being sent or stored. Therefore, the received or restored data stream is calculated by the same generator polynomial as described above. If the new CRC code result does not match the one calculated earlier, then this means that the data stream contains a data error.

## Peripheral Direct Memory Access – PDMA

- 6 channels with trigger source grouping
- 8-/16-/32-bit width data transfer
- Supports Address increment, decrement or fixed mode
- 4-level programmable channel priority
- Auto reload mode
- Supports trigger source: ADC, SPI, USART, UART, I<sup>2</sup>C, I<sup>2</sup>S, GPTM, MCTM, SCI and software request

The Peripheral Direct Memory Access controller, PDMA, moves data between the peripherals and the system memory on the AHB bus. Each PDMA channel has a source address, destination address, block length and transfer count. The PDMA can exclude the CPU intervention and avoid interrupt service routine execution. It improves system performance as the software does not need to connect each data movement operation.

## External Bus Interface – EBI

- Programmable interface for various memory types
- Translate the AHB transactions into the appropriate external device protocol
- Individual chip select signal for per memory bank
- Programmable timing to support a wide range of devices
- Automatic translation when AHB transaction width and external memory interface width is different
- Write buffer to decrease the stalling of the AHB write burst transaction
- Multiplexed and non-multiplexed address and data line configurations
  - Up to 21 address lines
  - Up to 16-bit data bus width

The external bus interface is able to access external parallel interface devices such as SRAM, Flash and LCD modules. The interface is memory mapped into the CPU internal address map. The data and address lines are multiplexed in order to reduce the number of pins required to connect to the external devices. The read/write timing of the bus can be adjusted to meet the timing specification of the external devices. Note the interface only supports asynchronous 8 or 16-bit bus interface.



## Universal Serial Bus Device Controller – USB

- Complies with USB 2.0 full-speed (12 Mbps) specification
- On-chip USB full-speed transceiver
- 1 control endpoint (EP0) for control transfer
- 3 single-buffered endpoints for bulk and interrupt transfer
- 4 double-buffered endpoints for bulk, interrupt and isochronous transfer
- 1,024 bytes EP-SRAM used as the endpoint data buffers

The USB device controller is compliant with the USB 2.0 full-speed specification. There is one control endpoint known as Endpoint 0 and seven configurable endpoints. A 1024-byte SRAM is used as the endpoint buffer. Each endpoint buffer size is programmable using corresponding registers, which provides maximum flexibility for various applications. The integrated USB full-speed transceiver helps to minimise the overall system complexity and cost. The USB functional block also contains the resume and suspend feature to meet the requirements of low-power consumption.

## Debug Support

- Serial Wire Debug Port – SW-DP
- 4 comparators for hardware breakpoint or code / literal patch
- 2 comparators for hardware watchpoints

## Package and Operation Temperature

- 33-pin QFN, 48/64-pin LQFP package
- Operation temperature range: -40°C to +85°C

# 3 Overview

## Device Information

**Table 1. Features and Peripheral List**

Peripherals		HT32F52342	HT32F52352
Main Flash (KB)		64	127.5
Option Bytes Flash (KB)		0.5	0.5
SRAM (KB)		8	16
Timers	MCTM		1
	GPTM		2
	SCTM		2
	BFTM		2
	RTC		1
	WDT		1
Communication	USB		1
	SPI		2
	USART		2
	UART		2
	I <sup>2</sup> C		2
	I <sup>2</sup> S		1
	SCI (ISO7816-3)		2
EBI			1
CRC-16/32			1
GPIO			Up to 51
EXTI			16
12-bit ADC			1
Number of channels			12 Channels
Comparator			2
CPU frequency			Up to 48 MHz
Operating voltage			2.0 V ~ 3.6 V
Operating temperature			-40° C ~ +85° C
Package			33-pin QFN, 48/64-pin LQFP

## Block Diagram

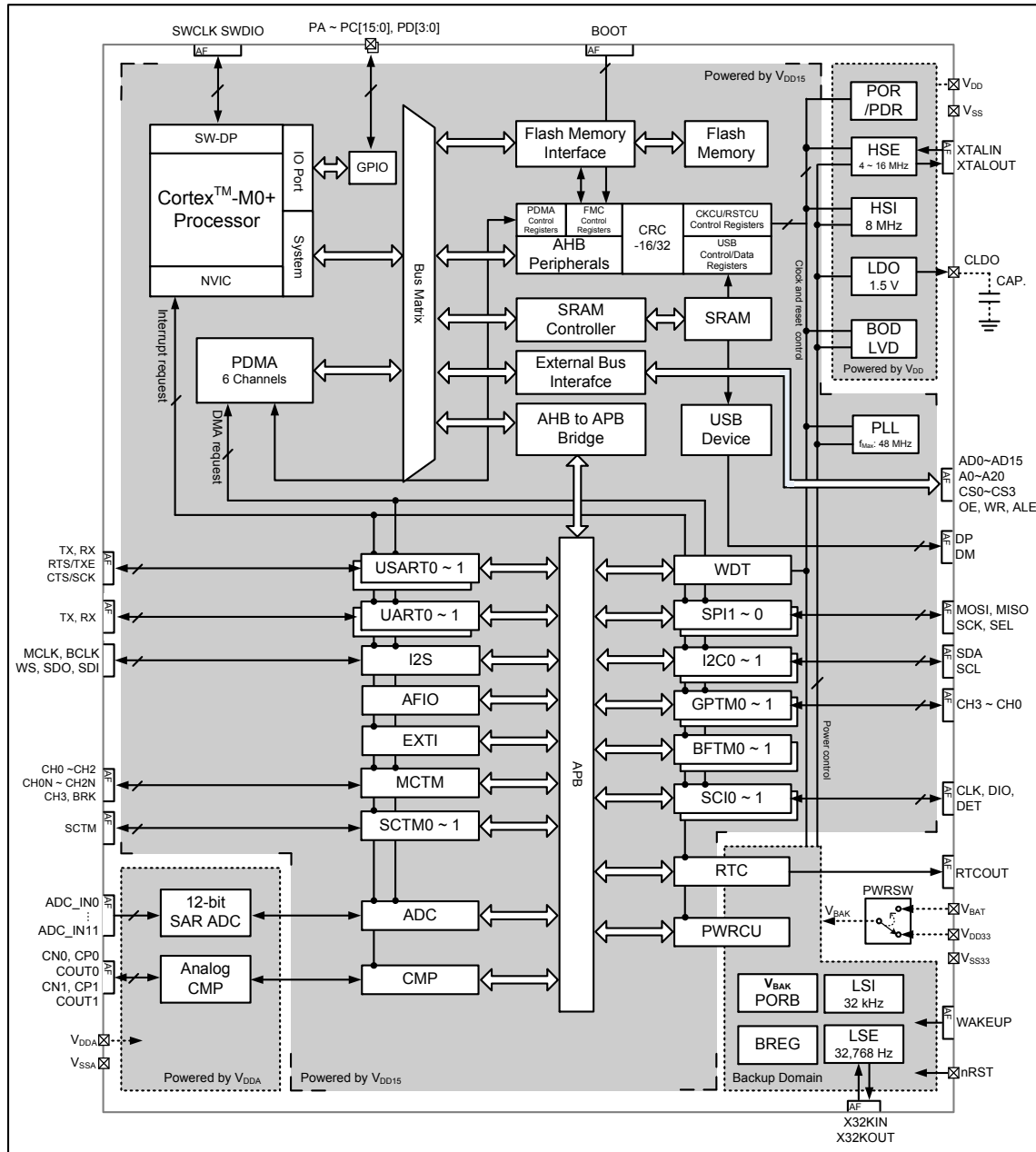


Figure 1. Block Diagram

## Memory Map

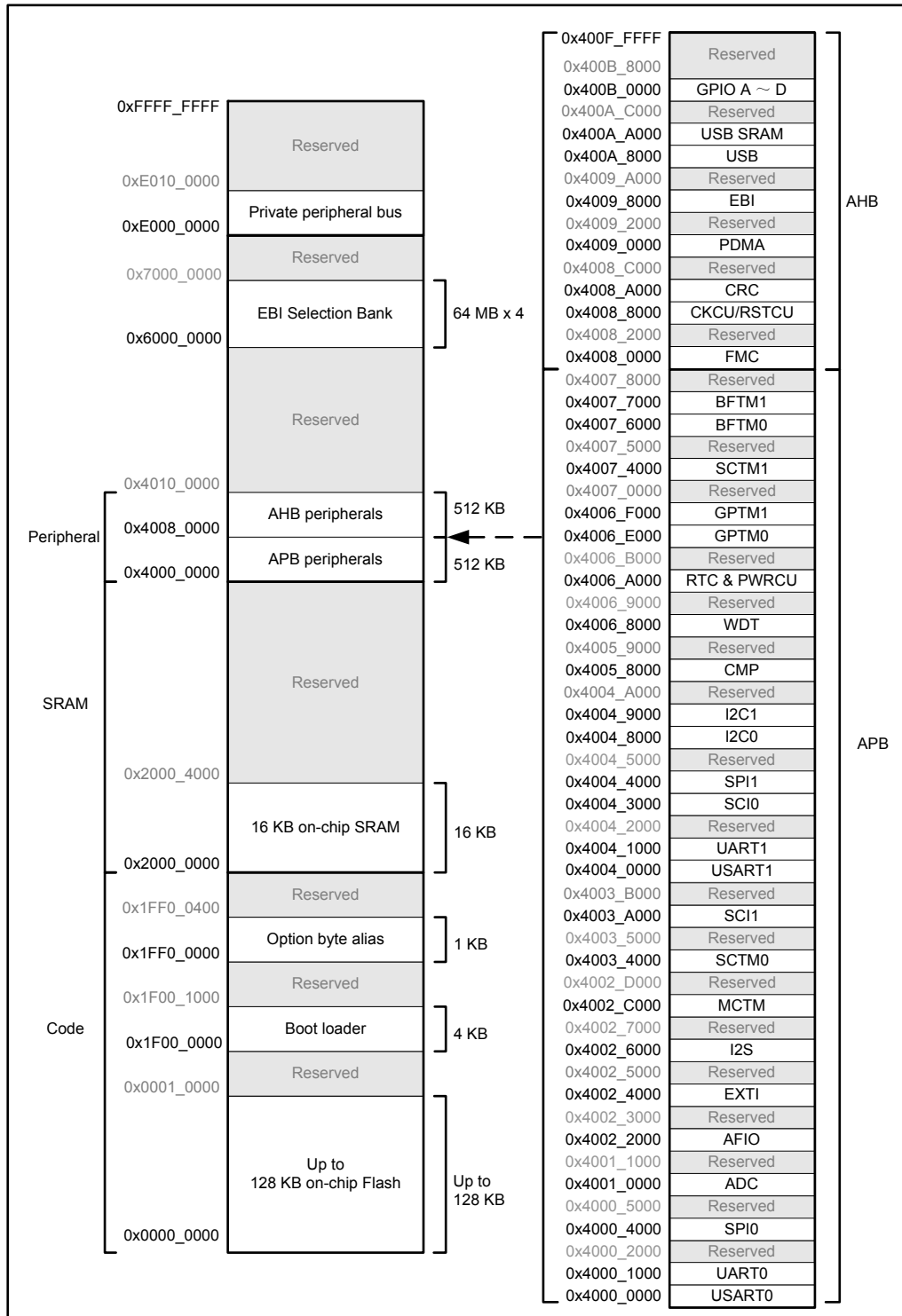


Figure 2. Memory Map

**Table 2. Register Map**

Start Address	End Address	Peripheral	Bus
0x4000_0000	0x4000_0FFF	USART0	APB
0x4000_1000	0x4000_1FFF	UART0	
0x4000_2000	0x4000_3FFF	Reserved	
0x4000_4000	0x4000_4FFF	SPI0	
0x4000_5000	0x4000_FFFF	Reserved	
0x4001_0000	0x4001_0FFF	ADC	
0x4001_1000	0x4002_1FFF	Reserved	
0x4002_2000	0x4002_2FFF	AFIO	
0x4002_3000	0x4002_3FFF	Reserved	
0x4002_4000	0x4002_4FFF	EXTI	
0x4002_5000	0x4002_BFFF	Reserved	
0x4002_6000	0x4002_6FFF	I2S	
0x4002_7000	0x4002_BFFF	Reserved	
0x4002_C000	0x4002_CFFF	MCTM	
0x4002_D000	0x4003_3FFF	Reserved	
0x4003_4000	0x4003_4FFF	SCTM0	
0x4003_5000	0x4003_9FFF	Reserved	
0x4003_A000	0x4003_AFFF	SCI1	
0x4003_B000	0x4003_FFFF	Reserved	
0x4004_0000	0x4004_0FFF	USART1	
0x4004_1000	0x4004_1FFF	UART1	
0x4004_2000	0x4004_2FFF	Reserved	
0x4004_3000	0x4004_3FFF	SCI0	
0x4004_4000	0x4004_4FFF	SPI1	
0x4004_5000	0x4004_7FFF	Reserved	
0x4004_8000	0x4004_8FFF	I2C0	
0x4004_9000	0x4004_9FFF	I2C1	
0x4004_A000	0x4005_7FFF	Reserved	
0x4005_8000	0x4005_8FFF	Comparator	
0x4005_9000	0x4006_7FFF	Reserved	
0x4006_8000	0x4006_8FFF	WDT	
0x4006_9000	0x4006_9FFF	Reserved	
0x4006_A000	0x4006_AFFF	RTC/PWRCU	
0x4006_B000	0x4006_DFFF	Reserved	
0x4006_E000	0x4006_EFFF	GPTM0	
0x4006_F000	0x4006_FFFF	GPTM1	
0x4007_0000	0x4007_3FFF	Reserved	
0x4007_4000	0x4007_4FFF	SCTM1	
0x4007_5000	0x4007_5FFF	Reserved	
0x4007_6000	0x4007_6FFF	BFTM0	
0x4007_7000	0x4007_7FFF	BFTM1	
0x4007_8000	0x4007_FFFF	Reserved	

Start Address	End Address	Peripheral	Bus
0x4008_0000	0x4008_1FFF	FMC	AHB
0x4008_2000	0x4008_7FFF	Reserved	
0x4008_8000	0x4008_9FFF	CKCU/RSTCU	
0x4008_A000	0x4008_BFFF	CRC	
0x4008_C000	0x4008_FFFF	Reserved	
0x4009_0000	0x4009_1FFF	PDMA Control Registers	
0x4009_2000	0x4009_7FFF	Reserved	
0x4009_8000	0x4009_9FFF	EBI Control Registers	
0x4009_A000	0x400A_7FFF	Reserved	
0x400A_8000	0x400A_BFFF	USB	
0x400A_C000	0x400A_FFFF	Reserved	
0x400B_0000	0x400B_1FFF	GPIOA	
0x400B_2000	0x400B_3FFF	GPIOB	
0x400B_4000	0x400B_5FFF	GPIOC	
0x400B_6000	0x400B_7FFF	GPIOD	
0x400B_8000	0x400F_FFFF	Reserved	

## Clock Structure

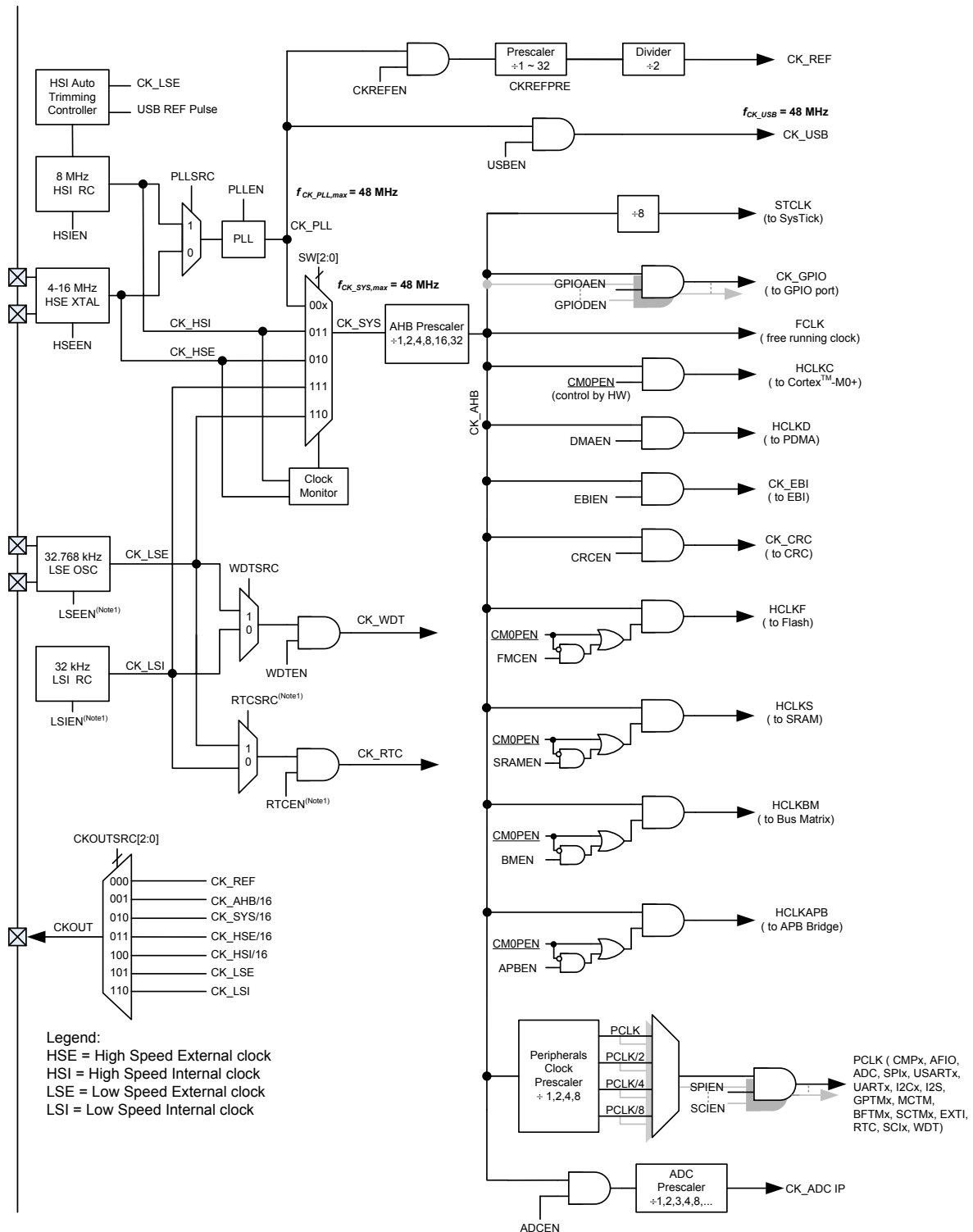
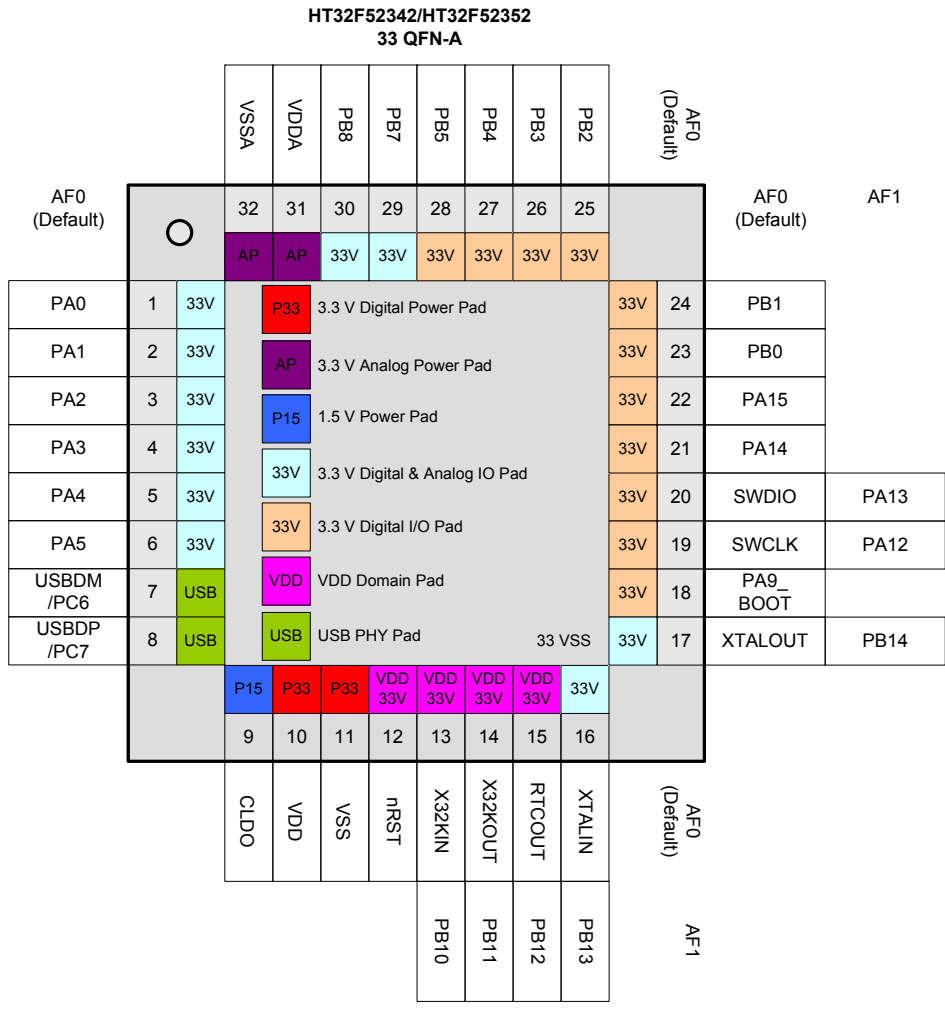


Figure 3. Clock Structure

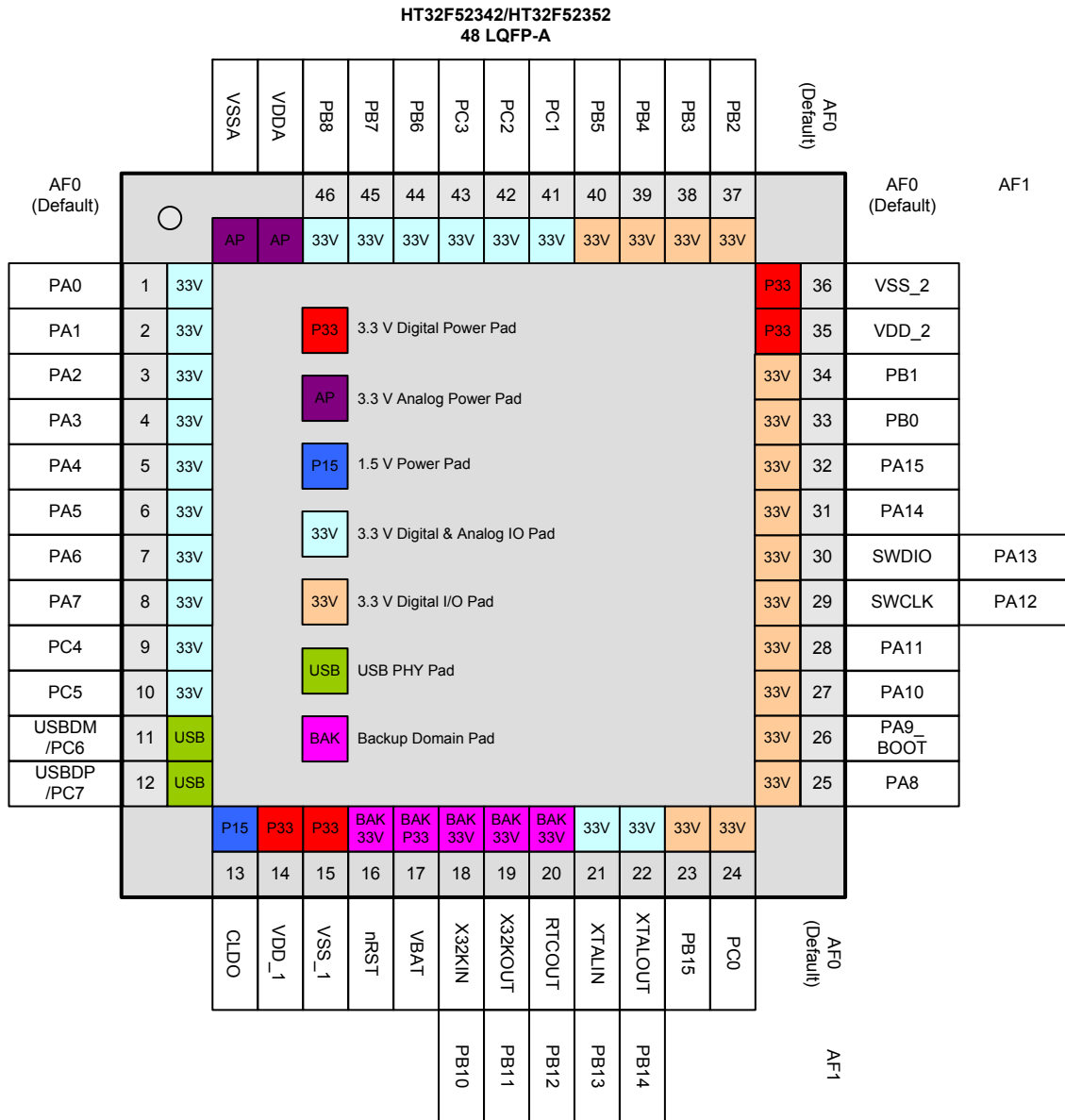
# 4 Pin Assignment



**Figure 4. 33-pin QFN Pin Assignment**

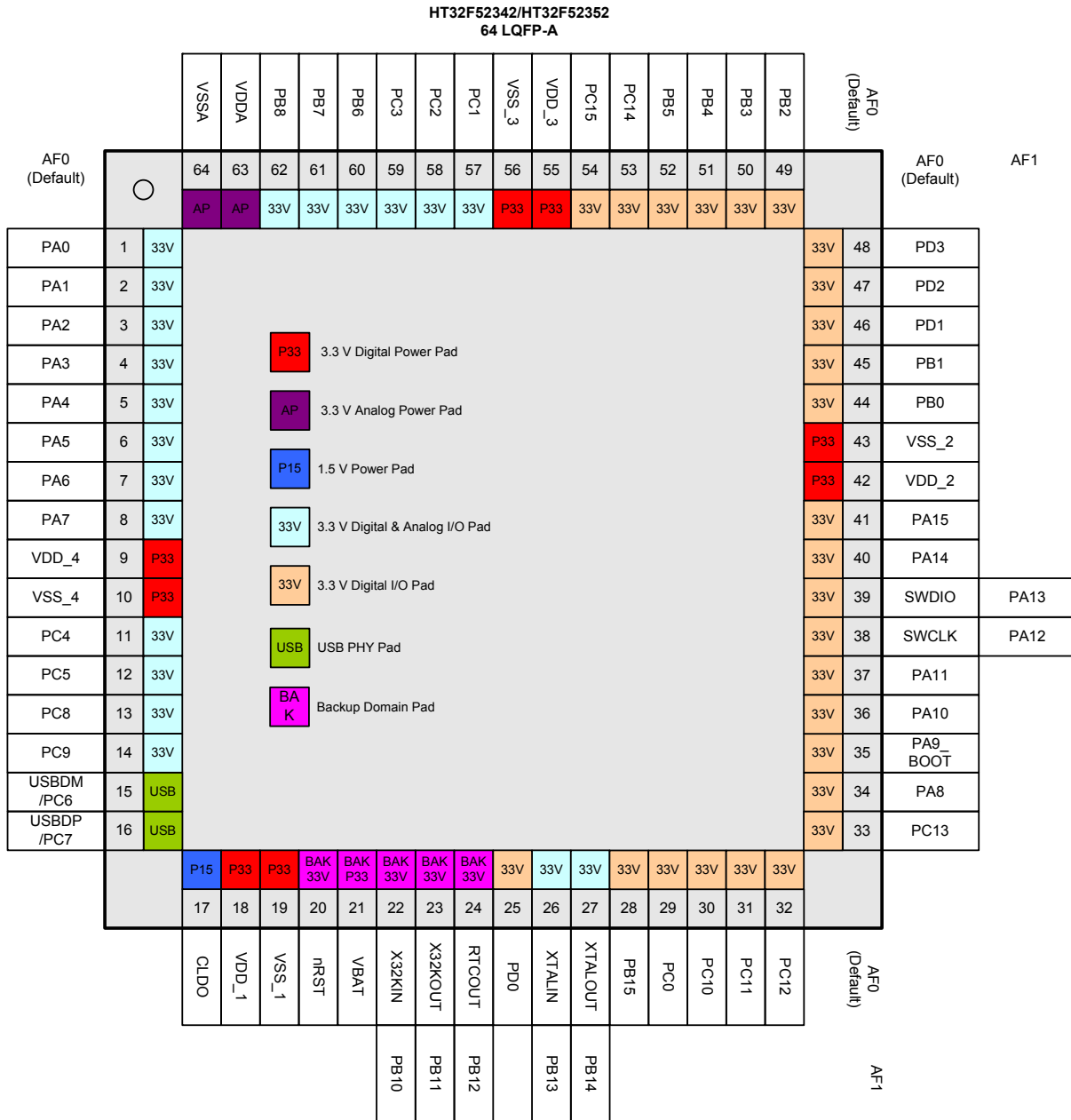
Pin Assignment





Pin Assignment

**Figure 5. 48-pin LQFP Pin Assignment**



Pin Assignment

**Figure 6. 64-pin LQFP Pin Assignment**

**Table 3. Pin Assignment for 33-pin QFN, 48/64-pin LQFP Package**

Package			Alternate Function Mapping																
64 LQFP	48 LQFP	33 QFN	AF0 System Default	AF1 GPIO	AF2 ADC	AF3 CMP	AF4 MCTM /GPTM	AF5 SPI	AF6 USART /UART	AF7 I2C	AF8 SCI	AF9 EBI	AF10 I2S	AF11 N/A	AF12 N/A	AF13 SCTM	AF14 N/A	AF15 System Other	
1	1	1	PA0		ADC_IN0		GT1_CH0	SPI1_SCK	USR0_RTS	I2C1_SCL	SCI0_CLK		I2S_WS						
2	2	2	PA1		ADC_IN1		GT1_CH1	SPI1_MOSI	USR0_CTS	I2C1_SDA	SCI0_DIO		I2S_BCLK						
3	3	3	PA2		ADC_IN2		GT1_CH2	SPI1_MISO	USR0_TX				I2S_SDO						
4	4	4	PA3		ADC_IN3		GT1_CH3	SPI1_SEL	USR0_RX				I2S_SDI						
5	5	5	PA4		ADC_IN4		GT0_CH0	SPI0_SCK	USR1_TX	I2C0_SCL	SCI1_CLK								
6	6	6	PA5		ADC_IN5		GT0_CH1	SPI0_MOSI	USR1_RX	I2C0_SDA	SCI1_DIO								
7	7		PA6		ADC_IN6		GT0_CH2	SPI0_MISO	USR1_RTS		SCI1_DET								
8	8		PA7		ADC_IN7		GT0_CH3	SPI0_SEL	USR1_CTS				I2S_MCLK						
9			VDD_4																
10			VSS_4																
11	9		PC4		ADC_IN8		GT0_CH0	SPI1_SEL	UR0_TX	I2C1_SCL		EBI_A19				SCTM0			
12	10		PC5		ADC_IN9		GT0_CH1	SPI1_SCK	UR0_RX	I2C1_SDA		EBI_A20				SCTM1			
13			PC8		ADC_IN10		GT0_CH2	SPI1_MOSI				EBI_A0							
14			PC9		ADC_IN11		GT0_CH3	SPI1_MISO				EBI_A1							
15	11	7	PC6				MT_CH2		USR0_TX	I2C0_SCL									
15	11	7	USBDM																
16	12	8	USBDP																
16	12	8	PC7				MT_CH2N		USR0_RX	I2C0_SDA									
17	13	9	CLDO																
18	14	10	VDD_1																
19	15	11	VSS_1																
20	16	12	nRST																
21	17		VBAT																
22	18	13	X32KIN	PB10															
23	19	14	X32KOUT	PB11															
24	20	15	RTCOUT	PB12														WAKEUP	
25			PD0							I2C0_SDA		EBI_A18	I2S_SDI			SCTM0			
26	21	16	XTALIN	PB13															
27	22	17	XTALOUT	PB14															
28	23		PB15				MT_CH0	SPI0_SEL	USR1_TX	I2C1_SCL		EBI_A16	I2S_MCLK						
29	24		PC0				MT_CH0N	SPI0_SCK	USR1_RX	I2C1_SDA		EBI_A17							
30			PC10				GT1_CH0	SPI1_SEL				EBI_AD13	I2S_WS						
31			PC11				GT1_CH1	SPI1_SCK				EBI_AD14	I2S_BCLK						
32			PC12				GT1_CH2	SPI1_MOSI	UR1_TX	I2C0_SCL		EBI_AD15	I2S_SDO						
33			PC13				GT1_CH3	SPI1_MISO	UR1_RX	I2C0_SDA		EBI_CS3	I2S_SDI						
34	25		PA8						USR0_TX		SCI1_CLK		I2S_MCLK						
35	26	18	PA9_BOOT					SPI0_MOSI			SCI1_DIO	EBI_A1	I2S_WS					CKOUT	
36	27		PA10				MT_CH1		USR0_RX		SCI0_DET								

Pin Assignment

Package			Alternate Function Mapping															
64 LQFP	48 LQFP	33 QFN	AF0 System Default	AF1 GPIO	AF2 ADC	AF3 CMP	AF4 MCTM /GPTM	AF5 SPI	AF6 USART /UART	AF7 I2C	AF8 SCI	AF9 EBI	AF10 I2S	AF11 N/A	AF12 N/A	AF13 SCTM	AF14 N/A	AF15 System Other
37	28		PA11				MT_CH1N	SPI0_MISO			SCI1_DET	EBI_A0	I2S_MCLK			SCTM0		
38	29	19	SWCLK	PA12														
39	30	20	SWDIO	PA13														
40	31	21	PA14				MT_CH0	SPI1_SEL	USR1_TX	I2C1_SCL	SCI0_CLK	EBI_AD0						
41	32	22	PA15				MT_CH0N	SPI1_SCK	USR1_RX	I2C1_SDA	SCI0_DIO	EBI_AD1				SCTM1		
42			VDD_2															
43			VSS_2															
44	33	23	PB0				MT_CH1	SPI1_MOSI	USR0_TX	I2C0_SCL		EBI_AD2						
45	34	24	PB1				MT_CH1N	SPI1_MISO	USR0_RX	I2C0_SDA		EBI_AD3						
46			PD1				MT_CH2		USR1_RTS		SCI0_CLK	EBI_AD10						
47			PD2				MT_CH2N		USR1_CTS		SCI0_DIO	EBI_AD11						
48			PD3				MT_CH3				SCI0_DET	EBI_AD12						
	35		VDD_2															
	36	33	VSS_2															
49	37	25	PB2				MT_CH2	SPI0_SEL	UR0_TX			EBI_AD4						
50	38	26	PB3				MT_CH2N	SPI0_SCK	UR0_RX			EBI_AD5				SCTM1		
51	39	27	PB4				MT_BRK	SPI0_MOSI	UR1_TX			EBI_AD6				SCTM0		
52	40	28	PB5				MT_BRK	SPI0_MISO	UR1_RX			EBI_AD7						
53			PC14				MT_CH3			I2C0_SCL		EBI_AD8						
54			PC15							I2C0_SDA		EBI_AD9				SCTM1		
55			VDD_3															
56			VSS_3															
57	41		PC1			CN0	MT_CH0	SPI1_SEL	UR1_TX			EBI_OE	I2S_MCLK					
58	42		PC2			CP0	MT_CH0N	SPI1_SCK				EBI_CS0						
59	43		PC3			COUT0		SPI1_MOSI	UR1_RX			EBI_WE						
60	44		PB6			CN1	MT_CH2	SPI1_MISO	UR0_TX		SCI1_CLK	EBI_ALE	I2S_BCLK					
61	45	29	PB7			CP1	MT_CH2N			I2C1_SCL	SCI1_DET	EBI_CS1	I2S_SDO					
62	46	30	PB8			COUT1	MT_CH3		UR0_RX	I2C1_SDA	SCI1_DIO	EBI_CS2	I2S_SDI					
63	47	31	VDDA															
64	48	32	VSSA															

**Table 4. Pin Description**

Pin Number			Pin Name	Type (Note1)	IO Structure (Note2)	Output Driving	Description
64LQFP	48LQFP	33QFN					Default Function (AF0)
1	1	1	PA0	AI/O	33V	4/8/12/16 mA	PA0
2	2	2	PA1	AI/O	33V	4/8/12/16 mA	PA1
3	3	3	PA2	AI/O	33V	4/8/12/16 mA	PA2
4	4	4	PA3	AI/O	33V	4/8/12/16 mA	PA3
5	5	5	PA4	AI/O	33V	4/8/12/16 mA	PA4
6	6	6	PA5	AI/O	33V	4/8/12/16 mA	PA5
7	7		PA6	AI/O	33V	4/8/12/16 mA	PA6
8	8		PA7	AI/O	33V	4/8/12/16 mA	PA7
9			VDD_4	P	—	—	Voltage for digital I/O
10			VSS_4	P	—	—	Ground reference for digital I/O
11	9		PC4	AI/O	33V	4/8/12/16 mA	PC4
12	10		PC5	AI/O	33V	4/8/12/16 mA	PC5
13			PC8	AI/O	33V	4/8/12/16 mA	PC8
14			PC9	AI/O	33V	4/8/12/16 mA	PC9
15	11	7	PC6	I/O	33V	4/8/12/16 mA	PC6
15	11	7	USBDM	AI/O	—	—	USB Differential data bus conforming to the Universal Serial Bus standard.
16	12	8	USBDP	AI/O	—	—	USB Differential data bus conforming to the Universal Serial Bus standard.
16	12	8	PC7	I/O	33V	4/8/12/16 mA	PC7
17	13	9	CLDO	P	—	—	Core power LDO 1.5 V output. It is recommended to connect a 2.2 uF capacitor as close as possible between this pin and VSS_1.
18	14	10	VDD_1	P	—	—	Voltage for digital I/O
19	15	11	VSS_1	P	—	—	Ground reference for digital I/O
20	16	12	nRST	I (BK)	33V_PU	—	External reset pin and external wakeup pin in the Power-Down mode
21	17		VBAT	P	—	—	Battery power input for the backup domain
22	18	13	PB10 <sup>Note 4</sup>	AI/O (BK)	33V	< 2 mA	X32KIN
23	19	14	PB11 <sup>Note 4</sup>	AI/O (BK)	33V	< 2 mA	X32KOUT
24	20	15	PB12 <sup>Note 4</sup>	I/O (BK)	33V	< 2 mA	RTCOUT
25			PD0	I/O	33V	4/8/12/16 mA	PD0
26	21	16	PB13	AI/O	33V	4/8/12/16 mA	XTALIN
27	22	17	PB14	AI/O	33V	4/8/12/16 mA	XTALOUT
28	23		PB15	I/O	33V	4/8/12/16 mA	PB15
29	24		PC0	I/O	33V	4/8/12/16 mA	PC0
30			PC10	I/O	33V	4/8/12/16 mA	PC10
31			PC11	I/O	33V	4/8/12/16 mA	PC11
32			PC12	I/O	33V	4/8/12/16 mA	PC12
33			PC13	I/O	33V	4/8/12/16 mA	PC13
34	25		PA8	I/O	33V_PU	4/8/12/16 mA	PA8
35	26	18	PA9	I/O	33V_PU	4/8/12/16 mA	PA9_BOOT
36	27		PA10	I/O	33V	4/8/12/16 mA	PA10
37	28		PA11	I/O	33V	4/8/12/16 mA	PA11
38	29	19	PA12	I/O	33V_PU	4/8/12/16 mA	SWCLK
39	30	20	PA13	I/O	33V_PU	4/8/12/16 mA	SWDIO
40	31	21	PA14	I/O	33V	4/8/12/16 mA	PA14
41	32	22	PA15	I/O	33V	4/8/12/16 mA	PA15
42			VDD_2	P	—	—	Voltage for digital I/O
43			VSS_2	P	—	—	Ground reference for digital I/O

Pin Number			Pin Name	Type (Note1)	IO Structure (Note2)	Output Driving	Description
64LQFP	48LQFP	33QFN					Default Function (AF0)
44	33	23	PB0	I/O	33V	4/8/12/16 mA	PB0
45	34	24	PB1	I/O	33V	4/8/12/16 mA	PB1
46			PD1	I/O	33V	4/8/12/16 mA	PD1
47			PD2	I/O	33V	4/8/12/16 mA	PD2
48			PD3	I/O	33V	4/8/12/16 mA	PD3
	35		VDD_2	P	—	—	Voltage for digital I/O
	36	33	VSS_2	P	—	—	Ground reference for digital I/O
49	37	25	PB2	I/O	33V	4/8/12/16 mA	PB2
50	38	26	PB3	I/O	33V	4/8/12/16 mA	PB3
51	39	27	PB4	I/O	33V	4/8/12/16 mA	PB4
52	40	28	PB5	I/O	33V	4/8/12/16 mA	PB5
53			PC14	I/O	33V	4/8/12/16 mA	PC14
54			PC15	I/O	33V	4/8/12/16 mA	PC15
55			VDD_3	P	—	—	Voltage for digital I/O
56			VSS_3	P	—	—	Ground reference for digital I/O
57	41		PC1	AI/O	33V	4/8/12/16 mA	PC1
58	42		PC2	AI/O	33V	4/8/12/16 mA	PC2
59	43		PC3	AI/O	33V	4/8/12/16 mA	PC3
60	44		PB6	AI/O	33V	4/8/12/16 mA	PB6
61	45	29	PB7	AI/O	33V	4/8/12/16 mA	PB7
62	46	30	PB8	AI/O	33V	4/8/12/16 mA	PB8
63	47	31	VDDA	P	—	—	Analog voltage for ADC and Comparator
64	48	32	VSSA	P	—	—	Ground reference for the ADC and Comparator

Note: 1. I = input, O = output, A = Analog port, P = power supply, PU = pull-up, BK = Back-up domain

2. 33V = 3.3 V tolerant.

3. The GPIOs are in an AF0 state after a V<sub>DD15</sub> power on reset (POR) except for the RTCOUT pin in the Backup Domain I/O. The RTCOUT pin is reset by the Backup Domain power-on-reset (PORB) or by the Backup Domain software reset (BAK\_RST bit in BAK\_CR register).

4. The backup domain of the I/O pins have a source current capability limitation of < 2 mA @ V<sub>DD</sub> = 3.3 V. The typical sink current is 4/8 mA configurable @ V<sub>DD</sub> = 3.3 V.

# 5 Electrical Characteristics

## Absolute Maximum Ratings

The following table shows the absolute maximum ratings of the device. These are stress ratings only. Stresses beyond absolute maximum ratings may cause permanent damage to the device. Note that the device is not guaranteed to operate properly at the maximum ratings. Exposure to the absolute maximum rating conditions for extended periods may affect device reliability.

**Table 5. Absolute Maximum Ratings**

Symbol	Parameter	Min	Max	Unit
V <sub>DD</sub>	External main supply voltage	V <sub>SS</sub> - 0.3	V <sub>SS</sub> + 3.6	V
V <sub>DDA</sub>	External analog supply voltage	V <sub>SSA</sub> - 0.3	V <sub>SSA</sub> + 3.6	V
V <sub>BAT</sub>	External battery supply voltage	V <sub>SS</sub> - 0.3	V <sub>SS</sub> + 3.6	V
V <sub>IN</sub>	Input voltage on I/O	V <sub>SS</sub> - 0.3	V <sub>DD</sub> + 0.3	V
T <sub>A</sub>	Ambient operating temperature range	-40	+85	°C
T <sub>STG</sub>	Storage temperature range	-55	+150	°C
T <sub>J</sub>	Maximum junction temperature	—	125	°C
P <sub>D</sub>	Total power dissipation	—	500	mW
V <sub>ESD</sub>	Electrostatic discharge voltage - human body mode	-4000	+4000	V

## Recommended DC Operating Conditions

**Table 6. Recommended DC Operating Conditions**

T<sub>A</sub> = 25°C, unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V <sub>DD</sub>	I/O operating voltage		2.0	3.3	3.6	V
V <sub>DDA</sub>	Analog operating voltage		2.5	3.3	3.6	V
V <sub>BAT</sub>	Battery supply operating voltage		2.0	3.3	3.6	V

## On-Chip LDO Voltage Regulator Characteristics

**Table 7. LDO Characteristics**

T<sub>A</sub> = 25°C, unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V <sub>LDO</sub>	Internal regulator output voltage	V <sub>DD</sub> ≥ 2.0 V Regulator input @ I <sub>LDO</sub> = 35 mA and voltage variant = ±5 %, after trimming.	1.425	1.5	1.57	V
I <sub>LDO</sub>	Output current	V <sub>DD</sub> = 2.0 V Regulator input @ V <sub>LDO</sub> = 1.5 V	—	35	—	mA
C <sub>LDO</sub>	External filter capacitor value for internal core power supply	The capacitor value is dependent upon the core power current consumption	—	2.2	—	μF

## Power Consumption

Table 8. Power Consumption Characteristics

T<sub>A</sub> = 25°C, unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
I <sub>DD</sub>	Supply Current (Run mode)	V <sub>DD</sub> = V <sub>BAT</sub> = 3.3 V, HSE = 8 MHz, PLL = 48 MHz, f <sub>HCLK</sub> = 48 MHz, f <sub>PCLK</sub> = 48 MHz, All peripherals enabled	—	20	—	mA
		V <sub>DD</sub> = V <sub>BAT</sub> = 3.3 V, HSE = 8 MHz, PLL = 48 MHz, f <sub>HCLK</sub> = 48 MHz, f <sub>PCLK</sub> = 48 MHz, All peripherals disabled	—	10	—	mA
		V <sub>DD</sub> = V <sub>BAT</sub> = 3.3 V, HSE off, PLL off, LSI on, f <sub>HCLK</sub> = 32 kHz, f <sub>PCLK</sub> = 32 kHz, All peripherals enabled	—	51	—	μA
		V <sub>DD</sub> = V <sub>BAT</sub> = 3.3 V, HSE off, PLL off, LSI on, f <sub>HCLK</sub> = 32 kHz, f <sub>PCLK</sub> = 32 kHz, All peripherals disabled	—	45	—	μA
	Supply Current (Sleep mode)	V <sub>DD</sub> = V <sub>BAT</sub> = 3.3 V, HSE = 8 MHz, PLL = 48 MHz, f <sub>HCLK</sub> = 0 MHz, f <sub>PCLK</sub> = 48 MHz, All peripherals enabled	—	—	—	mA
		V <sub>DD</sub> = V <sub>BAT</sub> = 3.3 V, HSE = 8 MHz, PLL = 48 MHz, f <sub>HCLK</sub> = 0 MHz, f <sub>PCLK</sub> = 48 MHz, All peripherals disabled	—	—	—	mA
	Supply Current (Deep-Sleep1 mode)	V <sub>DD</sub> = V <sub>BAT</sub> = 3.3 V, All clock off (HSE/PLL/f <sub>HCLK</sub> ), LDO in low power mode, LSI on, RTC on	—	40	—	μA
	Supply Current (Deep-Sleep2 mode)	V <sub>DD</sub> = V <sub>BAT</sub> = 3.3 V, All clock off (HSE/PLL/f <sub>HCLK</sub> ), LDO off (DMOS on), LSI on, RTC on	—	12	—	μA
	Supply Current (Power-Down mode)	V <sub>DD</sub> = V <sub>BAT</sub> = 3.3 V, LDO off, LSE on, LSI on, RTC on	—	—	—	μA
		V <sub>DD</sub> = V <sub>BAT</sub> = 3.3 V, LDO off, LSE off, LSI on, RTC off	—	2	—	μA
I <sub>BAT</sub>	Battery Supply Current (Power-Down mode)	V <sub>DD33</sub> not present, V <sub>BAT</sub> = 3.3 V, LDO off, LSE off, LSI on, RTC on	—	—	—	μA
		V <sub>DD</sub> not present, V <sub>BAT</sub> = 3.3 V, LDO off, LSE off, LSI on, RTC off	—	1.5	—	μA

- Note: 1. HSE means high speed external oscillator. HSI means 8 MHz high speed internal oscillator.  
 2. LSE means 32.768 kHz low speed external oscillator. LSI means 32 kHz low speed internal oscillator.  
 3. RTC means real time clock.  
 4. Code = while (1) { 208 NOP } executed in Flash.



## Reset and Supply Monitor Characteristics

**Table 9. V<sub>DD</sub> Power Reset Characteristics**

T<sub>A</sub> = 25°C, unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V <sub>POR</sub>	Power on reset threshold (Rising Voltage on V <sub>DD</sub> )	T <sub>A</sub> = -40°C~ +85°C	1.66	1.79	1.90	V
V <sub>PDR</sub>	Power down reset threshold (Falling Voltage on V <sub>DD</sub> )		1.49	1.64	1.78	V
V <sub>PORHYST</sub>	POR hysteresis	—	—	150	—	mV
t <sub>POR</sub>	Reset delay time	V <sub>DD</sub> = 3.3 V	—	0.1	0.2	ms

- Note: 1. Data based on characterisation results only, not tested in production.  
 2. Guaranteed by design, not tested in production.  
 3. If the LDO is turned on, the V<sub>DD</sub> POR has to be in the de-assertion condition. When the V<sub>DD</sub> POR is in the assertion state then the LDO will be turned off.

**Table 10. LVD/BOD Characteristics**

T<sub>A</sub> = 25°C, unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit	
V <sub>BOD</sub>	Voltage of Brown Out Detection	T <sub>A</sub> = -40°C~ 85°C After factory-trimmed (V <sub>DD</sub> Falling edge)	2.02	2.1	2.18	V	
V <sub>LVD</sub>	Voltage of Low Voltage Detection	T <sub>A</sub> = -40°C~ 85°C (V <sub>DD</sub> Falling edge)	LVDS = 000	2.17	2.25	2.33	V
			LVDS = 001	2.32	2.4	2.48	V
			LVDS = 010	2.47	2.55	2.63	V
			LVDS = 011	2.62	2.7	2.78	V
			LVDS = 100	2.77	2.85	2.93	V
			LVDS = 101	2.92	3.0	3.08	V
			LVDS = 110	3.07	3.15	3.23	V
LVDS = 111	3.22	3.3	3.38	V			
V <sub>LVDHTST</sub>	LVD hysteresis	V <sub>DD</sub> = 3.3 V	—	—	100	mV	
t <sub>suLVD</sub>	LVD Setup time	V <sub>DD</sub> = 3.3 V	—	—	—	5 μs	
t <sub>aiLVD</sub>	LVD active delay time	V <sub>DD</sub> = 3.3 V	—	—	—	μs	
I <sub>DDLVD</sub>	Operation current <sup>NOTE3</sup>	V <sub>DD</sub> = 3.3 V	—	—	5	15 μA	

- Note: 1. Data based on characterisation results only, not tested in production.  
 2. Guaranteed by design, not tested in production.  
 3. Bandgap current is not included.  
 4. LVDS field is in the PWRCU LVDCSR register

## External Clock Characteristics

**Table 11. High Speed External Clock (HSE) Characteristics**

$T_A = 25^\circ\text{C}$ , unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{DD}$	Operation Range	—	2.0	—	3.6	V
$f_{HSE}$	High Speed External oscillator frequency (HSE)	—	4	—	16	MHz
$C_{LHSE}$	Load capacitance	$V_{DD} = 3.3\text{ V}$ , $R_{ESR} = 100\ \Omega$ @ 16 MHz	—	—	22	pF
$R_{FHSE}$	Internal feedback resistor between XTALIN and XTALOUT pins	—	—	1	—	M $\Omega$
$R_{ESR}$	Equivalent Series Resistance*	$V_{DD} = 3.3\text{ V}$ , $C_L = 12\text{ pF}$ @ 16 MHz, HSEDR = 0 $V_{DD} = 2.4\text{ V}$ , $C_L = 12\text{ pF}$ @ 16 MHz, HSEDR = 1	—	—	160	$\Omega$
$D_{HSE}$	HSE oscillator Duty cycle	—	40	—	60	%
$I_{DDHSE}$	HSE oscillator current consumption	$V_{DD} = 3.3\text{ V}$ @ 16 MHz	—	TBD	—	mA
$I_{PWDHSE}$	HSE oscillator power down current	$V_{DD} = 3.3\text{ V}$	—	—	0.01	$\mu\text{A}$
$t_{SUHSE}$	HSE oscillator startup time	$V_{DD} = 3.3\text{ V}$	—	—	4	ms

**Table 12. Low Speed External Clock (LSE) Characteristics**

$T_A = 25^\circ\text{C}$ , unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{BAK}$	Operation Range	—	2.0	—	3.6	V
$f_{CK\_LSE}$	LSE Frequency	$V_{BAK} = 2.0\text{ V} \sim 3.6\text{ V}$	—	32.768	—	kHz
$R_F$	Internal feedback resistor	—	—	10	—	M $\Omega$
$R_{ESR}$	Equivalent Series Resistance	$V_{BAK} = 3.3\text{ V}$	30	—	TBD	K $\Omega$
$C_L$	Recommended load capacitances	$V_{BAK} = 3.3\text{ V}$	6	—	TBD	pF
$I_{DDLSE}$	Oscillator supply current (High current mode)	$f_{CK\_LSE} = 32.768\text{ kHz}$ , $R_{ESR} = 50\text{ K}\Omega$ , $C_L \geq 7\text{ pF}$ $V_{BAK} = 2.0\text{ V} \sim 2.7\text{ V}$ $T_A = -40^\circ\text{C} \sim +85^\circ\text{C}$	—	3.3	6.3	$\mu\text{A}$
	Oscillator supply current (Low current mode)	$f_{CK\_LSE} = 32.768\text{ kHz}$ , $R_{ESR} = 50\text{ K}\Omega$ , $C_L < 7\text{ pF}$ $V_{BAK} = 2.0\text{ V} \sim 3.6\text{ V}$ $T_A = -40^\circ\text{C} \sim +85^\circ\text{C}$	—	1.8	3.3	$\mu\text{A}$
	Power down current	—	—	—	0.01	$\mu\text{A}$
$t_{SU\_LSE}$	Startup time (Low current mode)	$f_{CK\_LSE} = 32.768\text{ kHz}$ , $V_{BAK} = 2.0\text{ V} \sim 3.6\text{ V}$	500	—	—	ms

Note: The following guidelines are recommended to increase the stability of the crystal circuit of the HSE / LSE clock in the PCB layout:

- The crystal oscillator should be located as close as possible to the MCU to keep the trace lengths as short as possible to reduce any parasitic capacitance.
- Shield lines in the vicinity of the crystal by using a ground plane to isolate signals and reduce noise.
- Keep any high frequency signal lines away from the crystal area to prevent any crosstalk adverse effects.

## Internal Clock Characteristics

**Table 13. High Speed Internal Clock (HSI) Characteristics**

$T_A = 25^\circ\text{C}$ , unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{DD}$	Operation Range		2.0		3.6	V
$f_{HSI}$	HSI Frequency	$V_{DD} = 3.3\text{ V @ } 25^\circ\text{C}$	—	8	—	MHz
$ACC_{HSI}$	Factory calibrated HSI oscillator frequency accuracy	$V_{DD} = 3.3\text{ V}, T_A = 25^\circ\text{C}$	-2	—	2	%
		$V_{DD} = 2.5\text{ V} \sim 3.6\text{ V}, T_A = -40^\circ\text{C} \sim +85^\circ\text{C}$	-3	—	3	%
		$V_{DD} = 2.0\text{ V} \sim 3.6\text{ V}, T_A = -40^\circ\text{C} \sim +85^\circ\text{C}$	-4	—	4	%
Duty	Duty cycle	$f_{HSI} = 8\text{ MHz}$	35	—	65	%
$I_{DDHSI}$	Oscillator supply current	$f_{HSI} = 8\text{ MHz}$		300	500	$\mu\text{A}$
	Power down current				0.05	$\mu\text{A}$
$t_{suHSI}$	Startup time	$f_{HSI} = 8\text{ MHz}$	-	-	10	$\mu\text{s}$

**Table 14. Low Speed Internal Clock (LSI) Characteristics**

$T_A = 25^\circ\text{C}$ , unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$f_{LSI}$	Low Speed Internal Oscillator Frequency (LSI)	$V_{DD} = 3.3\text{ V}, T_A = -40^\circ\text{C} \sim +85^\circ\text{C}$	21	32	43	kHz
$ACC_{LSI}$	LSI Frequency accuracy	After factory-trimmed, $V_{DD} = 3.3\text{ V}, T_A = 25^\circ\text{C}$	-10	—	+10	%
$I_{DDLSI}$	LSI Oscillator Operating current	$V_{DD} = 3.3\text{ V}, T_A = 25^\circ\text{C}$	—	0.4	0.8	$\mu\text{A}$
$t_{suLSI}$	LSI Oscillator startup time	$V_{DD} = 3.3\text{ V}, T_A = 25^\circ\text{C}$	—	—	100	$\mu\text{s}$

## PLL Characteristics

Table 15. PLL Characteristics

T<sub>A</sub> = 25°C, unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
f <sub>PLLIN</sub>	PLL input clock	—	4	—	16	MHz
f <sub>CK_PLL</sub>	PLL output clock	—	16	—	48	MHz
t <sub>LOCK</sub>	PLL lock time	—	—	200	—	μs

## Memory Characteristics

Table 16. Flash Memory Characteristics

T<sub>A</sub> = 25°C, unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
N <sub>ENDU</sub>	Number of guaranteed program/erase cycles before failure. (Endurance)	T <sub>A</sub> = -40°C ~ +85°C	10	—	—	K cycles
t <sub>RET</sub>	Data retention time	T <sub>A</sub> = -40°C ~ +85°C	10	—	—	Years
t <sub>PROG</sub>	Word programming time	T <sub>A</sub> = -40°C ~ +85°C	20	—	—	μs
t <sub>ERASE</sub>	Page erase time	T <sub>A</sub> = -40°C ~ +85°C	2	—	—	ms
t <sub>MERASE</sub>	Mass erase time	T <sub>A</sub> = -40°C ~ +85°C	10	—	—	ms

## I/O Port Characteristics

Table 17. I/O Port Characteristics

T<sub>A</sub> = 25°C, unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit	
I <sub>IL</sub>	Low level input current	3.3 V IO	V <sub>I</sub> = V <sub>SS</sub> , On-chip pull-up resistor disabled.	—	—	3	μA
		Reset pin		—	—	3	μA
I <sub>IH</sub>	High level input current	3.3 V IO	V <sub>I</sub> = V <sub>DD</sub> , On-chip pull-down resistor disabled.	—	—	3	μA
		Reset pin		—	—	3	μA
V <sub>IL</sub>	Low level input voltage	3.3 V IO	-0.5	—	V <sub>DD</sub> * 0.35	V	
		Reset pin	-0.5	—	V <sub>DD</sub> * 0.35	V	
V <sub>IH</sub>	High level input voltage	3.3 V IO	V <sub>DD</sub> * 0.65	—	V <sub>DD</sub> + 0.5	V	
		Reset pin	V <sub>DD</sub> * 0.65	—	V <sub>DD</sub> + 0.5	V	
V <sub>HYS</sub>	Schmitt trigger input voltage hysteresis	3.3 V IO	—	0.12 * V <sub>DD</sub>	—	mV	
		Reset pin	—	0.12 * V <sub>DD</sub>	—	mV	

Symbol	Parameter	Conditions	Min	Typ	Max	Unit	
I <sub>OL</sub>	Low level output current (GPIO Sink current)	3.3 V IO 4 mA drive, V <sub>OL</sub> = 0.4 V	4	—	—	mA	
		3.3 V IO 8 mA drive, V <sub>OL</sub> = 0.4 V	8	—	—	mA	
		3.3 V IO 12 mA drive, V <sub>OL</sub> = 0.4 V	12	—	—	mA	
		3.3 V IO 16 mA drive, V <sub>OL</sub> = 0.4 V	16	—	—	mA	
		Backup Domain IO drive @ V <sub>DD</sub> = 3.3 V, V <sub>OL</sub> = 0.4 V, PB10, PB11, PB12	4	—	—	mA	
I <sub>OH</sub>	High level output current (GPIO Source current)	3.3 V I/O 4 mA drive, V <sub>OH</sub> = V <sub>DD</sub> - 0.4 V	4	—	—	mA	
		3.3 V I/O 8 mA drive, V <sub>OH</sub> = V <sub>DD</sub> - 0.4 V	8	—	—	mA	
		3.3 V I/O 12 mA drive, V <sub>OH</sub> = V <sub>DD</sub> - 0.4 V	12	—	—	mA	
		3.3 V I/O 16 mA drive, V <sub>OH</sub> = V <sub>DD</sub> - 0.4 V	16	—	—	mA	
		Backup Domain IO drive @ V <sub>DD</sub> = 3.3 V, V <sub>OH</sub> = V <sub>DD</sub> - 0.4 V, PB10, PB11, PB12.	—	—	2	mA	
V <sub>OL</sub>	Low level output voltage	3.3 V 4 mA drive IO, I <sub>OL</sub> = 4 mA	—	—	0.4	V	
		3.3 V 8 mA drive IO, I <sub>OL</sub> = 8 mA	—	—	0.4	V	
		3.3 V 12 mA drive IO, I <sub>OL</sub> = 12 mA	—	—	0.4	V	
		3.3 V 16 mA drive IO, I <sub>OL</sub> = 16 mA	—	—	0.4	V	
		Backup Domain IO Sink Current = 4 mA (Low driving strength)	V <sub>DD</sub> = 2.7 V~3.6 V	—	—	0.4	V
			V <sub>DD</sub> = 2.0 V~2.7 V	—	—	0.6	V
		Backup Domain IO Sink Current = 8 mA (High driving strength)	V <sub>DD</sub> = 2.7 V~3.6 V	—	—	0.4	V
V <sub>DD</sub> = 2.0 V~2.7 V	—		—	0.6	V		
V <sub>OH</sub>	High level output voltage	3.3 V 4 mA drive IO, I <sub>OH</sub> = 4 mA	V <sub>DD</sub> - 0.4	—	—	V	
		3.3 V 8 mA drive IO, I <sub>OH</sub> = 8 mA	V <sub>DD</sub> - 0.4	—	—	V	
		3.3 V 12 mA drive IO, I <sub>OL</sub> = 12 mA	V <sub>DD</sub> - 0.4	—	—	V	
		3.3 V 16 mA drive IO, I <sub>OL</sub> = 16 mA	V <sub>DD</sub> - 0.4	—	—	V	
		Backup Domain IO Source Current = 2mA	V <sub>DD</sub> = 2.7 V~3.6 V	2.4	—	—	V
			V <sub>DD</sub> = 2.0 V~2.7 V	V <sub>DD</sub> - 0.4	—	—	V
R <sub>PU</sub>	Internal pull-up resistor	3.3 V I/O	—	46	—	kΩ	
R <sub>PD</sub>	Internal pull-down resistor	3.3 V I/O	—	46	—	kΩ	

## ADC Characteristics

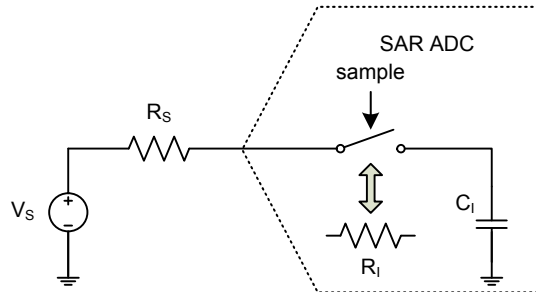
Table 18. ADC Characteristics

T<sub>A</sub> = 25°C, unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V <sub>DDA</sub>	Operating voltage	—	2.7	3.3	3.6	V
V <sub>ADDCIN</sub>	A/D Converter input voltage range	—	0	—	V <sub>REF+</sub>	V
V <sub>REF+</sub>	A/D Converter Reference voltage	—	—	V <sub>DDA</sub>	V <sub>DDA</sub>	V
I <sub>ADC</sub>	Current consumption	V <sub>DDA</sub> = 3.3 V	—	1	TBD	mA
I <sub>ADC_DN</sub>	Power down current consumption	V <sub>DDA</sub> = 3.3 V	—	—	0.1	μA
f <sub>ADC</sub>	A/D Converter clock	—	0.7	—	16	MHz
f <sub>S</sub>	Sampling rate	—	0.05	—	1	MHz
t <sub>DL</sub>	Data latency	—	—	12.5	—	1/f <sub>ADC</sub> Cycles
t <sub>S&amp;H</sub>	Sampling & hold time	—	—	3.5	—	1/f <sub>ADC</sub> Cycles
t <sub>ADCCONV</sub>	A/D Converter conversion time	—	—	16	—	1/f <sub>ADC</sub> Cycles
R <sub>I</sub>	Input sampling switch resistance	—	—	—	1	kΩ
C <sub>I</sub>	Input sampling capacitance	No pin/pad capacitance included	—	16	—	pF
t <sub>SU</sub>	Startup up time	—	—	—	1	μs
N	Resolution	—	—	12	—	bits
INL	Integral Non-linearity error	f <sub>S</sub> = 750 kHz, V <sub>DDA</sub> = 3.3 V	—	±2	±5	LSB
DNL	Differential Non-linearity error	f <sub>S</sub> = 750 kHz, V <sub>DDA</sub> = 3.3 V	—	±1	—	LSB
E <sub>O</sub>	Offset error	—	—	—	±10	LSB
E <sub>G</sub>	Gain error	—	—	—	±10	LSB

Note: 1. Guaranteed by design, not tested in production.

- The figure below shows the equivalent circuit of the A/D Converter Sample-and-Hold input stage where C<sub>I</sub> is the storage capacitor, R<sub>I</sub> is the resistance of the sampling switch and R<sub>S</sub> is the output impedance of the signal source V<sub>S</sub>. Normally the sampling phase duration is approximately, 3.5/f<sub>ADC</sub>. The capacitance, C<sub>I</sub>, must be charged within this time frame and it must be ensured that the voltage at its terminals becomes sufficiently close to V<sub>S</sub> for accuracy. To guarantee this, R<sub>S</sub> is not allowed to have an arbitrarily large value.



**Figure 7. ADC Sampling Network Model**

The worst case occurs when the extremities of the input range (0V and  $V_{REF}$ ) are sampled consecutively. In this situation a sampling error below  $\frac{1}{4}$  LSB is ensured by using the following equation:

$$R_s < \frac{3.5}{f_{ADC} C_i \ln(2^{N+2})} - R_i$$

Where  $f_{ADC}$  is the ADC clock frequency and N is the ADC resolution ( $N = 12$  in this case). A safe margin should be considered due to the pin/pad parasitic capacitances, which are not accounted for in this simple model.

If, in a system where the A/D Converter is used, there are no rail-to-rail input voltage variations between consecutive sampling phases,  $R_s$  may be larger than the value indicated by the equation above.

## Comparator Characteristics

Table 19. Comparator Characteristics

T<sub>A</sub> = 25°C, unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit	
V <sub>DDA</sub>	Operating voltage	Comparator mode	2.4	3.3	3.6	V	
V <sub>IN</sub>	Input Common Mode Voltage Range	CP or CN	V <sub>SSA</sub>	—	V <sub>DDA</sub>	V	
V <sub>IOS</sub>	Input offset voltage <sup>(1)</sup>	T <sub>A</sub> = 25°C	-15	—	15	mV	
V <sub>hys</sub>	Input Hysteresis	No hysteresis (CMPnHM [1:0] = 00)	—	0	—	mV	
		Low hysteresis (CMPnHM [1:0] = 01)	—	30	—	mV	
		Middle hysteresis (CMPnHM [1:0] = 10)	—	70	—	mV	
		High hysteresis (CMPnHM [1:0] = 11)	—	100	—	mV	
t <sub>RT</sub>	Response time Input Overdrive = ±100mV	High Speed mode	V <sub>DDA</sub> ≥ 2.7 V	—	50	100	ns
			V <sub>DDA</sub> < 2.7 V	—	100	250	
		Low Speed mode	—	2	5	μs	
I <sub>CMP</sub>	Current Consumption V <sub>DDA</sub> = 3.3 V	High Speed mode	—	130	—	μA	
		Low Speed mode	—	30	—	μA	
t <sub>CMPST</sub>	Comparator Startup Time	Comparator enabled to output valid.	—	—	50	μs	
I <sub>CMP_DN</sub>	Power Down Supply Current	CMPEN = 0 CVREFEN = 0 CVREFOE=0	—	—	0.1	μA	
<b>Comparator Voltage Reference (CVR)</b>							
V <sub>CVR</sub>	Output Range		V <sub>SSA</sub>	—	V <sub>DDA</sub>	V	
N <sub>Bits</sub>	CVR Scaler Resolution			6		bits	
t <sub>CVRST</sub>	Setting Time	CVR scaler setting time from CVREF = “000000” to “111111”	—	—	100	μs	
I <sub>CVR</sub>	Current Consumption V <sub>DDA</sub> = 3.3 V	CVREFEN=1, CMPREFOE=0	—	65	—	μA	
		CVREFEN=1, CVREFOE=1	—	80	110	μA	

Note: Guaranteed by design, not tested in production.

## SCTM/GPTM/MCTM Characteristics

Table 20. SCTM/GPTM/MCTM Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
f <sub>TM</sub>	Timer clock source for GPTM and MCTM	—	—	—	48	MHz
t <sub>RES</sub>	Timer resolution time	—	1	—	—	f <sub>TM</sub>
f <sub>EXT</sub>	External single frequency on channel 1 ~ 4	—	—	—	1/2	f <sub>TM</sub>
RES	Timer resolution	—	—	—	16	bits



## I<sup>2</sup>C Characteristics

Table 21. I<sup>2</sup>C Characteristics

Symbol	Parameter	Standard mode		Fast mode		Fast mode plus		Unit
		Min	Max	Min	Max	Min	Max	
f <sub>SCL</sub>	SCL clock frequency	—	100	—	400	—	1000	kHz
t <sub>SCL(H)</sub>	SCL clock high time	4.5	—	1.125	—	0.45	—	μs
t <sub>SCL(L)</sub>	SCL clock low time	4.5	—	1.125	—	0.45	—	μs
t <sub>FALL</sub>	SCL and SDA fall time	—	1.3	—	0.34	—	0.135	μs
t <sub>RISE</sub>	SCL and SDA rise time	—	1.3	—	0.34	—	0.135	μs
t <sub>SU(SDA)</sub>	SDA data setup time	500	—	125	—	50	—	ns
t <sub>H(SDA)</sub>	SDA data hold time	0	—	0	—	0	—	ns
t <sub>SU(STA)</sub>	START condition setup time	500	—	125	—	50	—	ns
t <sub>H(STA)</sub>	START condition hold time	0	—	0	—	0	—	ns
t <sub>SU(STO)</sub>	STOP condition setup time	500	—	125	—	50	—	ns

Note: 1. Guaranteed by design, not tested in production.

2. To achieve 100kHz standard mode, the peripheral clock frequency must be higher than 2MHz.

3. To achieve 400kHz fast mode, the peripheral clock frequency must be higher than 8MHz.

4. To achieve 1MHz fast mode plus, the peripheral clock frequency must be higher than 20MHz.

5. The above characteristic parameters of the I<sup>2</sup>C bus timing are based on: SEQ\_FILTER = 01 and COMB\_FILTER\_En is disabled.

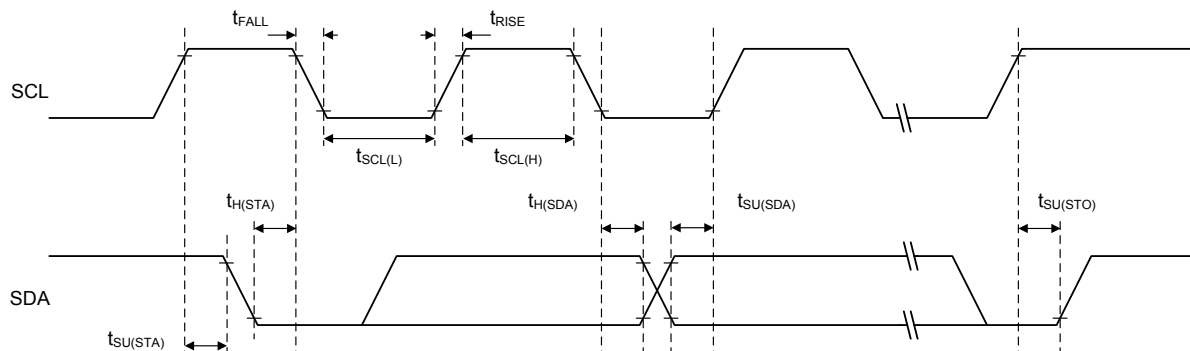


Figure 8. I<sup>2</sup>C Timing Diagrams

## SPI Characteristics

Table 22. SPI Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>SPI Master Mode</b>						
$f_{SCK}$ ( $1/t_{SCK}$ )	SPI master output SCK clock frequency	Master mode, SPI peripheral clock frequency $f_{PCLK}$	—	—	$f_{PCLK}/2$	MHz
$t_{SCK(H)}$ $t_{SCK(L)}$	SCK clock high and low time		$t_{SCK}/2 - 2$	—	$t_{SCK}/2 + 1$	ns
$t_{V(MO)}$	Data output valid time	—	—	—	5	ns
$t_{H(MO)}$	Data output hold time	—	2	—	—	ns
$t_{SU(MI)}$	Data input setup time	—	5	—	—	ns
$t_{H(MI)}$	Data input hold time	—	5	—	—	ns
<b>SPI Slave Mode</b>						
$f_{SCK}$ ( $1/t_{SCK}$ )	SPI master output SCK clock frequency	Slave mode, SPI peripheral clock frequency $f_{PCLK}$	—	—	$f_{PCLK}/3$	MHz
Duty <sub>SCK</sub>	SPI slave input SCK clock duty cycle		30	—	70	%
$t_{SU(SEL)}$	SEL enable setup time	—	3 $t_{PCLK}$	—	—	ns
$t_{H(SEL)}$	SEL enable hold time	—	2 $t_{PCLK}$	—	—	ns
$t_{A(SO)}$	Data output access time	—	—	—	3 $t_{PCLK}$	ns
$t_{DIS(SO)}$	Data output disable time	—	—	—	10	ns
$t_{V(SO)}$	Data output valid time	—	—	—	25	ns
$t_{H(SO)}$	Data output hold time	—	15	—	—	ns
$t_{SU(SI)}$	Data input setup time	—	5	—	—	ns
$t_{H(SI)}$	Data input hold time	—	4	—	—	ns

Note:  $t_{SCK} = 1/f_{SCK}$ ;  $t_{PCLK} = 1/f_{PCLK}$ . SPI output (input) clock frequency  $f_{SCK}$ ; SPI peripheral clock frequency  $f_{PCLK}$ .

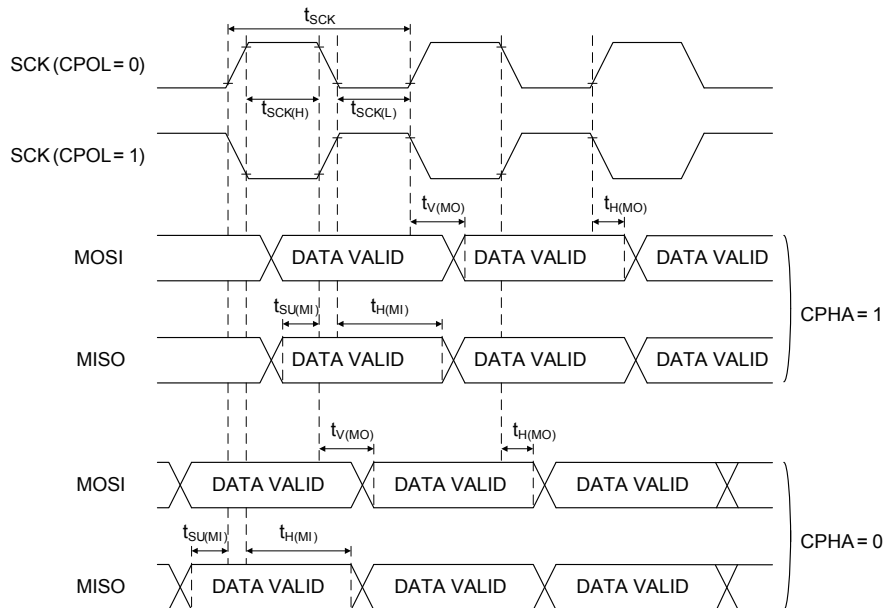


Figure 9. SPI Timing Diagrams – SPI Master Mode

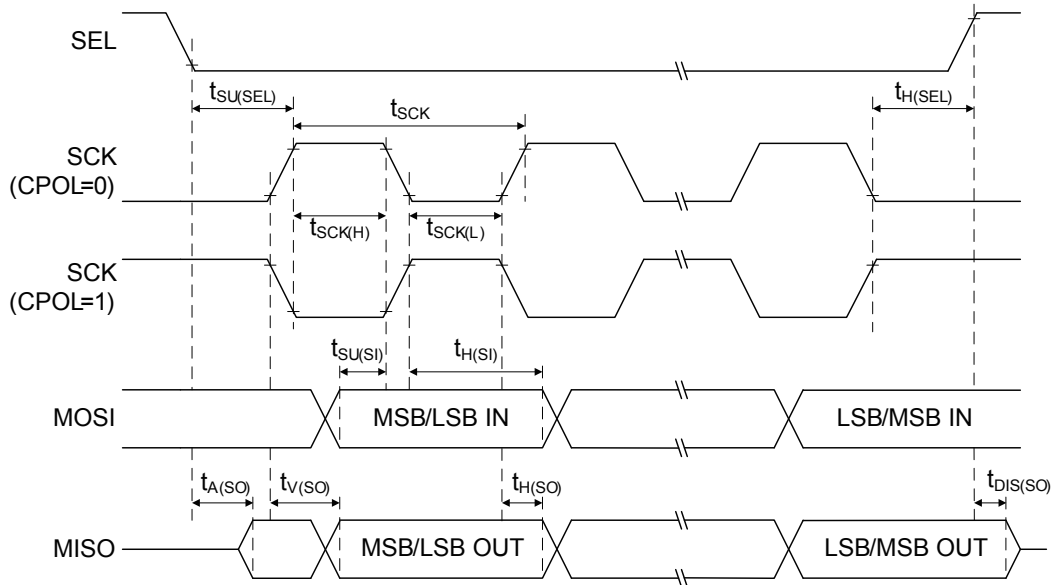
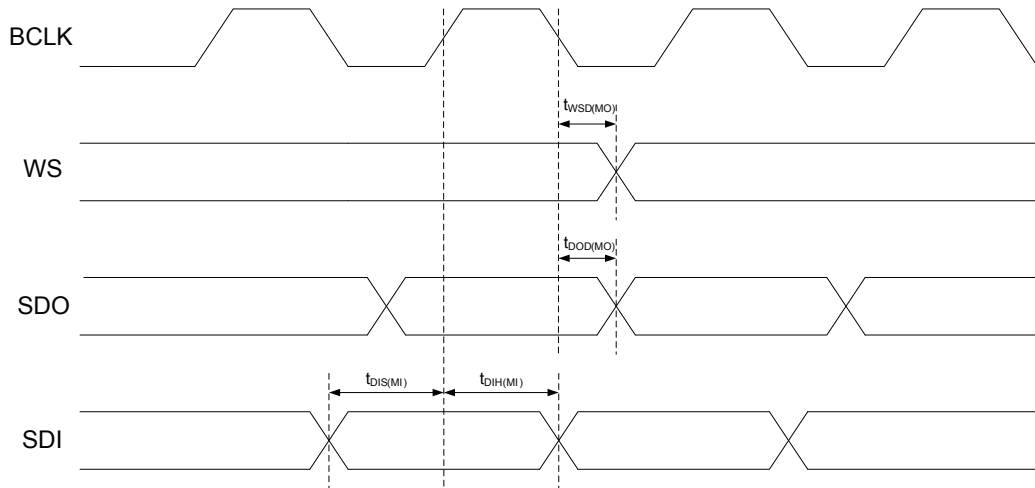


Figure 10. SPI Timing Diagrams – SPI Slave Mode with CPHA=1

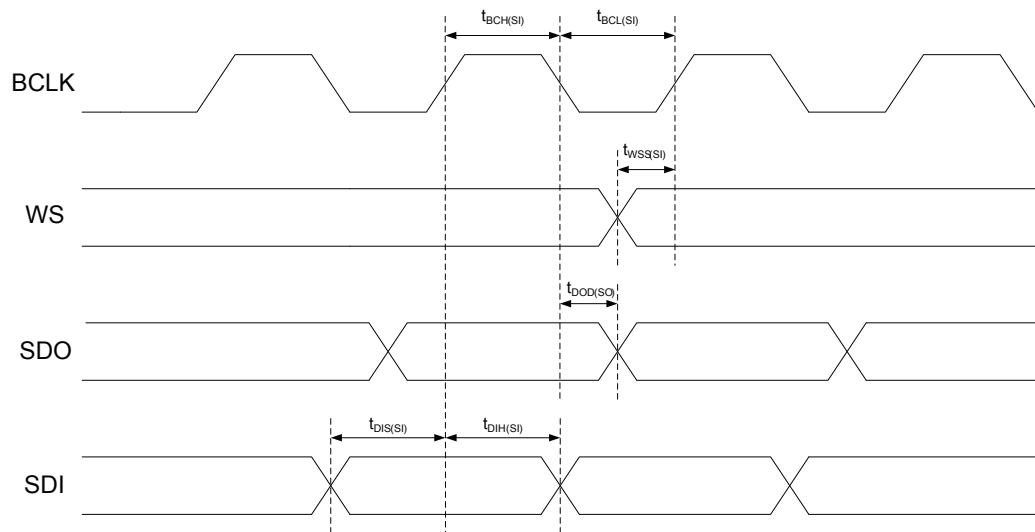
## I<sup>2</sup>S Characteristics

Table 23. I<sup>2</sup>S Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>I<sup>2</sup>S Master mode</b>						
$t_{WSD(MO)}$	WS output to BCLK delay	—	—	TBD	—	ns
$t_{DOD(MO)}$	Data output to BCLK delay	—	—	TBD	—	ns
$t_{DIS(MI)}$	Data input setup time	—	—	TBD	—	ns
$t_{DIH(MI)}$	Data input hold time	—	—	TBD	—	ns
<b>I<sup>2</sup>S Slave mode</b>						
$t_{BCH(SI)}$	BCLK high pulse width	—	—	TBD	—	ns
$t_{BCL(SI)}$	BCLK low pulse width	—	—	TBD	—	ns
$t_{WSS(SI)}$	WS input setup time	—	—	TBD	—	ns
$t_{DOD(SO)}$	Data output to BCLK delay	—	—	TBD	—	ns
$t_{DIS(SI)}$	Data input setup time	—	—	TBD	—	ns
$t_{DIH(SI)}$	Data input hold time	—	—	TBD	—	ns



**Figure 11. Timing of I<sup>2</sup>S Master Mode**



**Figure 12. Timing of I<sup>2</sup>S Slave Mode**

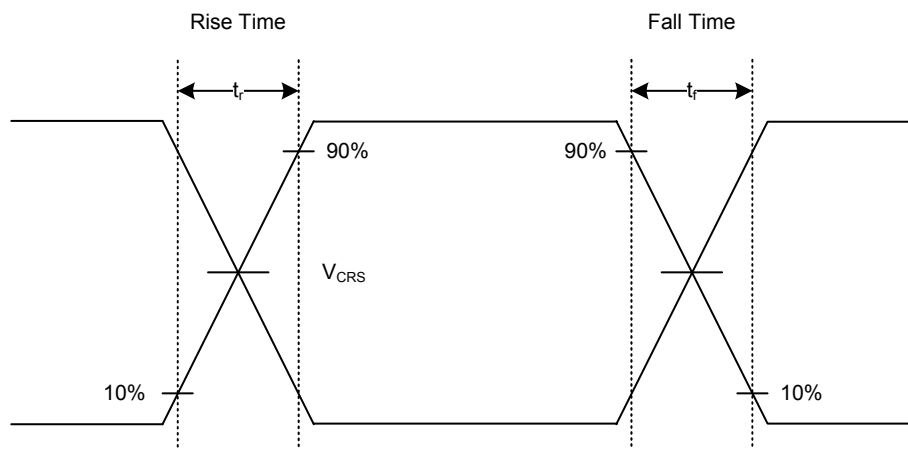
## USB Characteristics

The USB interface is USB-IF certified - Full Speed.

**Table 24. USB DC Electrical Characteristics**

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{DD}$	USB operating voltage	—	3.0	—	3.6	V
$V_{DI}$	Differential input sensitivity	$ USB_{DP} - USB_{DM} $	0.2	—	—	V
$V_{CM}$	Common mode voltage range	—	0.8	—	2.5	V
$V_{SE}$	Single-ended receiver threshold	—	0.8	—	2.0	V
$V_{OL}$	Pad output low voltage	RL of 1.5 kΩ to $V_{DD33}$	0	—	0.3	V
$V_{OH}$	Pad output high voltage		2.8	—	3.6	V
$V_{CRS}$	Differential output signal cross-point voltage		1.3	—	2.0	V
$Z_{DRV}$	Driver output resistance	—	—	10	—	Ω
$C_{IN}$	Transceiver pad capacitance	—	—	—	20	pF

- Note: 1. Guaranteed by design, not tested in production.  
 2. The USB functionality is ensured down to 2.7V but for not the full USB electrical characteristics which will experience degradation in the 2.7V to 3.0V  $V_{DD}$  voltage range.  
 3. RL is the load connected to the USB driver USBDP.



**Figure 13. USB Signal Rise Time and Fall Time and Cross-Point Voltage ( $V_{CRS}$ ) Definition**

**Table 25. USB AC Electrical Characteristics**

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$t_r$	Rise time	$C_L = 50$ pF	4	—	20	ns
$t_f$	Fall time	$C_L = 50$ pF	4	—	20	ns
$t_{r/f}$	Rise time / fall time matching	$t_{r/f} = t_r / t_f$	90	—	110	%

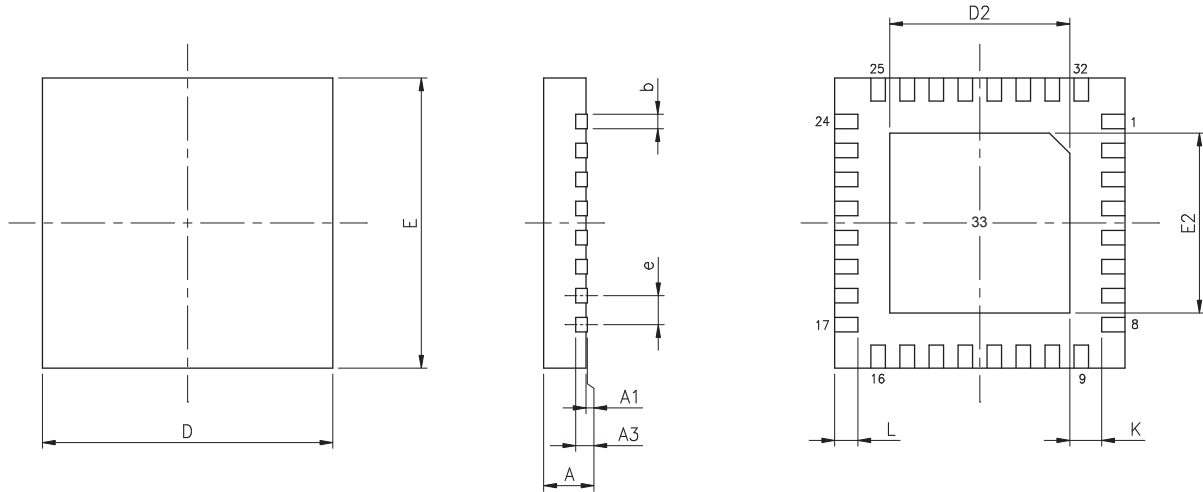
## 6 Package Information

Note that the package information provided here is for consultation purposes only. As this information may be updated at regular intervals users are reminded to consult the [Holtek website](#) for the latest version of the [package information](#).

Additional supplementary information with regard to packaging is listed below. Click on the relevant section to be transferred to the relevant website page.

- Further Package Information (include Outline Dimensions, Product Tape and Reel Specifications)
- Packing Materials Information
- Carton information

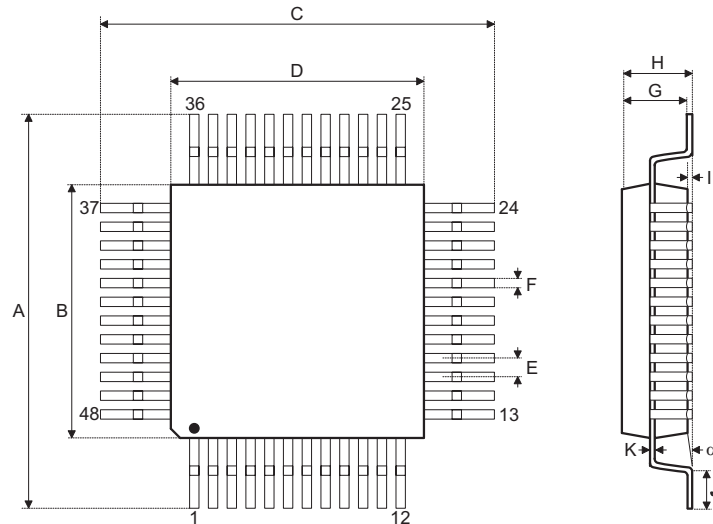
## SAW Type 33-pin (4mm×4mm) QFN Outline Dimensions



Symbol	Dimensions in inch		
	Min.	Nom.	Max.
A	0.028	0.030	0.031
A1	0.000	0.001	0.002
A3	—	0.008 BSC	—
b	0.006	0.008	0.010
D	—	0.157 BSC	—
E	—	0.157 BSC	—
e	—	0.016 BSC	—
D2	0.104	0.106	0.108
E2	0.104	0.106	0.108
L	0.014	0.016	0.018
K	0.008	—	—

Symbol	Dimensions in mm		
	Min.	Nom.	Max.
A	0.700	0.750	0.800
A1	0.000	0.020	0.050
A3	—	0.203 BSC	—
b	0.150	0.200	0.250
D	—	4.000 BSC	—
E	—	4.000 BSC	—
e	—	0.400 BSC	—
D2	2.650	2.700	2.750
E2	2.650	2.700	2.750
L	0.350	0.400	0.450
K	0.200	—	—

## 48-pin LQFP (7mm×7mm) Outline Dimensions

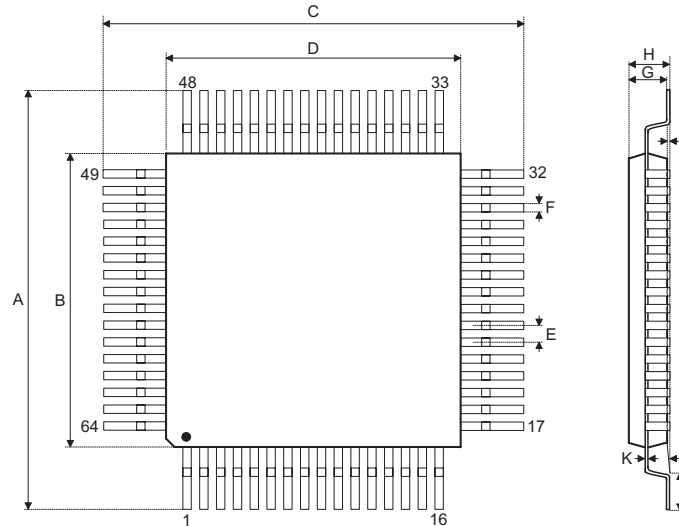


Symbol	Dimensions in inch		
	Min.	Nom.	Max.
A	—	0.354 BSC	—
B	—	0.276 BSC	—
C	—	0.354 BSC	—
D	—	0.276 BSC	—
E	—	0.0197 BSC	—
F	0.007	0.009	0.011
G	0.053	0.055	0.057
H	—	—	0.063
I	0.002	—	0.006
J	0.018	0.024	0.030
K	0.004	—	0.008
$\alpha$	0°	—	7°

Symbol	Dimensions in mm		
	Min.	Nom.	Max.
A	—	9.0 BSC	—
B	—	7.0 BSC	—
C	—	9.0 BSC	—
D	—	7.0 BSC	—
E	—	0.5 BSC	—
F	0.17	0.22	0.27
G	1.35	1.4	1.45
H	—	—	1.60
I	0.05	—	0.15
J	0.45	0.60	0.75
K	0.09	—	0.20
$\alpha$	0°	—	7°



## 64-pin LQFP (7mm×7mm) Outline Dimensions



Symbol	Dimensions in inch		
	Min.	Nom.	Max.
A	—	0.354 BSC	—
B	—	0.276 BSC	—
C	—	0.354 BSC	—
D	—	0.276 BSC	—
E	—	0.016 BSC	—
F	0.005	0.007	0.009
G	0.053	0.055	0.057
H	—	—	0.063
I	0.002	—	0.006
J	0.018	0.024	0.030
K	0.004	—	0.008
α	0°	—	7°

Symbol	Dimensions in mm		
	Min.	Nom.	Max.
A	—	9.0 BSC	—
B	—	7.0 BSC	—
C	—	9.0 BSC	—
D	—	7.0 BSC	—
E	—	0.4 BSC	—
F	0.13	0.18	0.23
G	1.35	1.4	1.45
H	—	—	1.60
I	0.05	—	0.15
J	0.45	0.60	0.75
K	0.09	—	0.20
α	0°	—	7°

Copyright© 2016 by HOLTEK SEMICONDUCTOR INC.

The information appearing in this Data Sheet is believed to be accurate at the time of publication. However, Holtek assumes no responsibility arising from the use of the specifications described. The applications mentioned herein are used solely for the purpose of illustration and Holtek makes no warranty or representation that such applications will be suitable without further modification, nor recommends the use of its products for application that may present a risk to human life due to malfunction or otherwise. Holtek's products are not authorized for use as critical components in life support devices or systems. Holtek reserves the right to alter its products without prior notification. For the most up-to-date information, please visit our web site at <http://www.holtek.com.tw/en/home>.